

Silicon photonics:

a new technology platform to enable
low cost and high performance
photonics

L. Pavesi



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**DEPARTMENT OF PHYSICS
Nanoscience Laboratory**

Outline

- Silicon Photonics
- State of the art
- Silicon Photonics for lab-on-a-chip
- NanoSilicon photonics
- Conclusion



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The experts look ahead

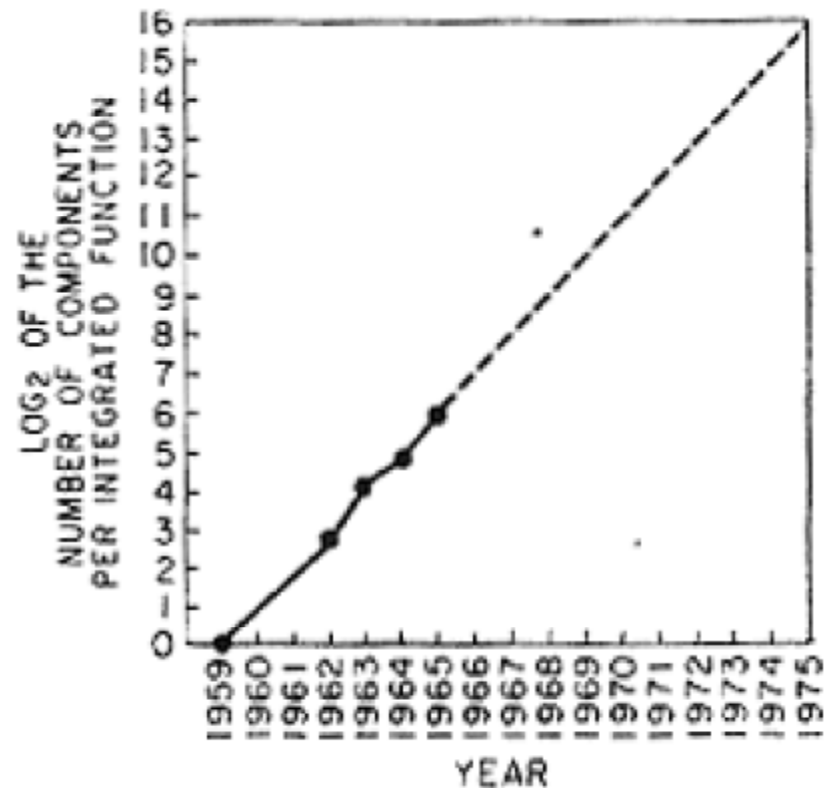
Cramming more components onto integrated circuits

With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squashing many as 65,000 components on a single silicon chip

By Gordon E. Moore

Director, Research and Development Laboratories, Fairchild Semiconductor Division of Fairchild Camera and Instrument Corp.

Electronics, Volume 38, Number 8, April 19, 1965



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18-11-10



The experts look ahead

Cramming more components onto integrated circuits

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By Gordon E. Moore

Director, Research and Development Laboratories, Fairchild Semiconductor
division of Fairchild Camera and Instrument Corp.

Objective: reduce the cost per single transistor



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Birth of the PIC Concept

"There is a conviction that the new miniaturized optical circuitry will prove useful... We must wait a while longer to find out how useful this new technology will become."



THE BELL SYSTEM TECHNICAL JOURNAL

DEVOTED TO THE SCIENTIFIC AND ENGINEERING
ASPECTS OF ELECTRICAL COMMUNICATION

Volume 48

September 1969

Number 7

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Integrated Optics: An Introduction

By STEWART E. MILLER

(Manuscript received January 29, 1969)

This paper outlines a proposal for a miniature form of laser beam circuitry. Index of refraction changes of the order of 10^{-2} or 10^{-3} in a substrate such as glass allow guided laser beams of width near 10 microns. Photolithographic techniques may permit simultaneous construction of complex circuit patterns. This paper also indicates possible miniature forms for a laser, modulator, and hybrids. If realized, this new art would facilitate isolating the laser circuit assembly from thermal, mechanical, and acoustic ambient changes through small overall size; economy should ultimately result.

I. INTRODUCTION

Laboratory work and experimental repeater work at laser wavelengths (0.4 to $10 + \mu\text{m}$) has been carried out by interconnecting the oscillators, modulators, detectors, and so on, using a form of extremely short-range radio. A freely propagating beam has been reflected around corners, occasionally refocused with lenses to avoid energy loss resulting from beam spreading, and often sheltered by tubular enclosures from refractive distortions resulting from thermal gradients in the ambient air. Typical separations between components range from a few centimeters to a foot; aggregations of apparatus in a single-channel experimental laser repeater are measured

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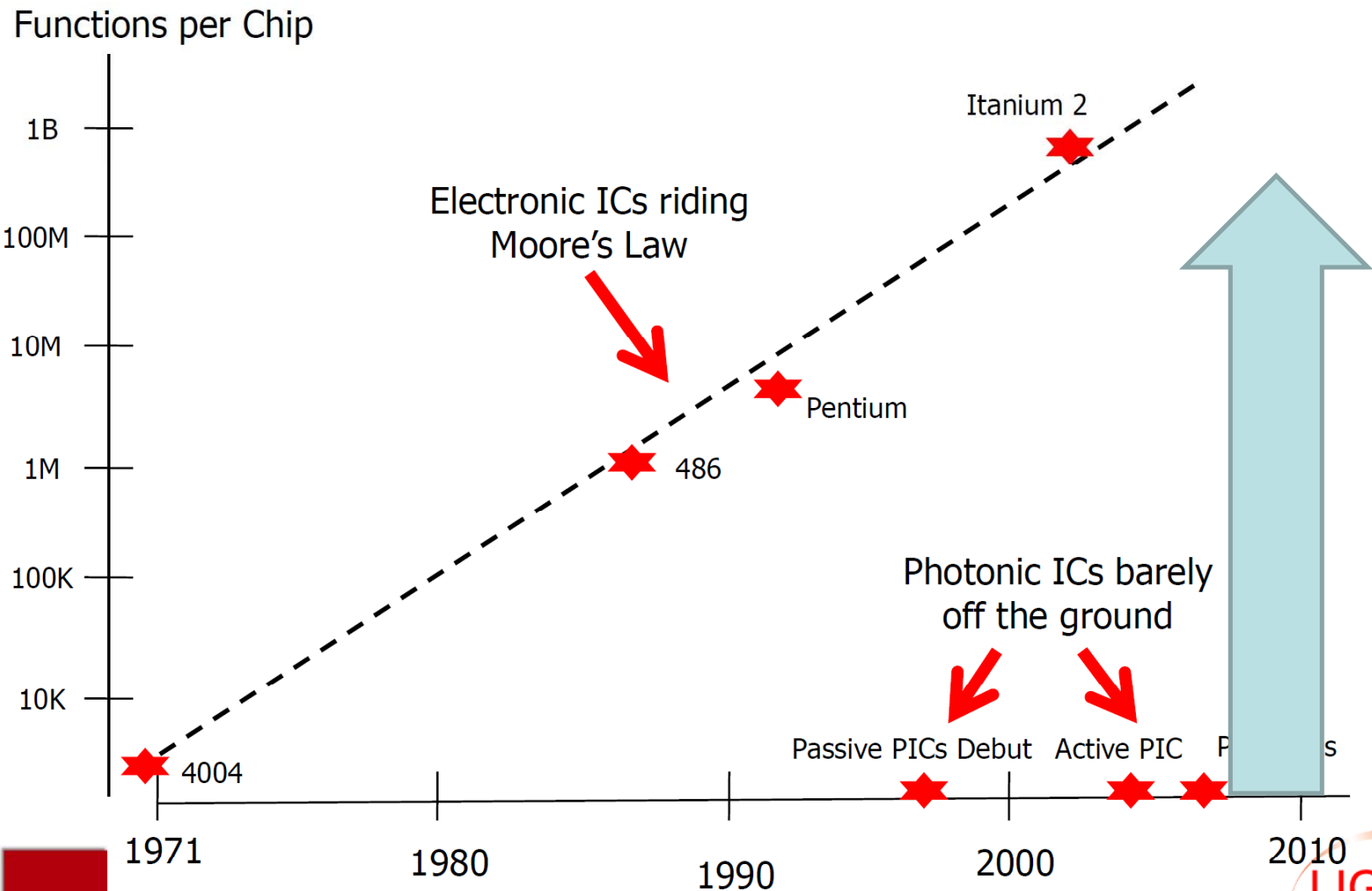


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29 January 1969

Comparing Technology Progress



Sources: Intel and Heavy Reading, 2008

HEAVY
READING

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Technology Comparison: Optics vs. ICs

Technologies	Semiconductor IC	Optical Components
Repeatable building block	Transistors	None (LD, PD, Mod, Filter, Isolator...)
Uniform material base	Silicon	None (InP, GaAs, Si...)
Dominant manufacturing process	CMOS	None (Hybrid, monolithic, active, passive...)

Source: J. P. Morgan

No standardized technology for optical components manufacturing

Technology Comparison: Optics vs. ICs vs. Silicon Photonics

Technologies	Optical Components	Semiconductor IC	Silicon Photonics
Repeatable building block	None (LD, PD, Mod, Filter, Isolator...)	Transistors	LD,PD, microrings,
Uniform material base	None (InP, GaAs, Si...)	Silicon	Silicon
Dominant manufacturing process	None (Hybrid, monolithic, active, passive...)	CMOS	CMOS

Source: J. P. Morgan

No standardized technology for optical components manufacturing

Silicon photonics

Photonic devices produced within
standard silicon factory and with
standard silicon processing



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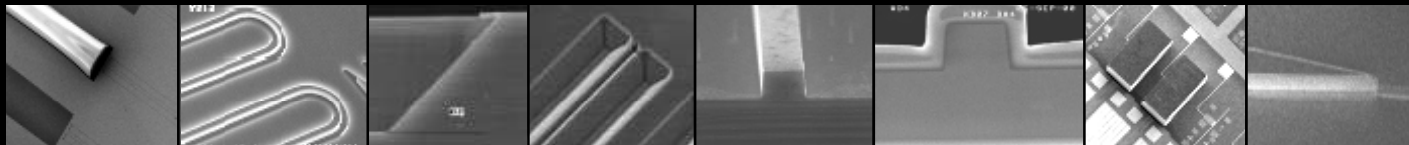
Silicon pro's and cons

- Transparent on 1.3-1.5 μm
 - CMOS compatibility
 - Low cost
 - High index contrast, small footprint
-
- No electro-optic effect
 - No detection in 1.3-1.5 μm region
 - High index contrast coupling
 - Lacks efficient light emission



The Opportunity of Silicon Photonics

- Enormous (\$ billions) CMOS infrastructure, process learning, and capacity
 - Draft continued investment in Moore's law
- Potential to integrate multiple optical devices
- Micromachining could provide smart packaging
- Potential to converge computing & communications



To benefit from this optical wafers
must run alongside existing product.
CMOS PHOTONICS



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Cost = paradigm change

- 200 mm Si wafer has 125,000 - 0.5 mm sized dies
- Cost processed CMOS wafers \$2,000,000
- Cost per die: \$16
- Laser size: 10x100 microns.
- Cost per laser: \$ 0.064
- This is just like estimating the cost of transistors. They are free. Only the PIC cost matters.
- Emphasis is moved from components to the system



Silicon photonics

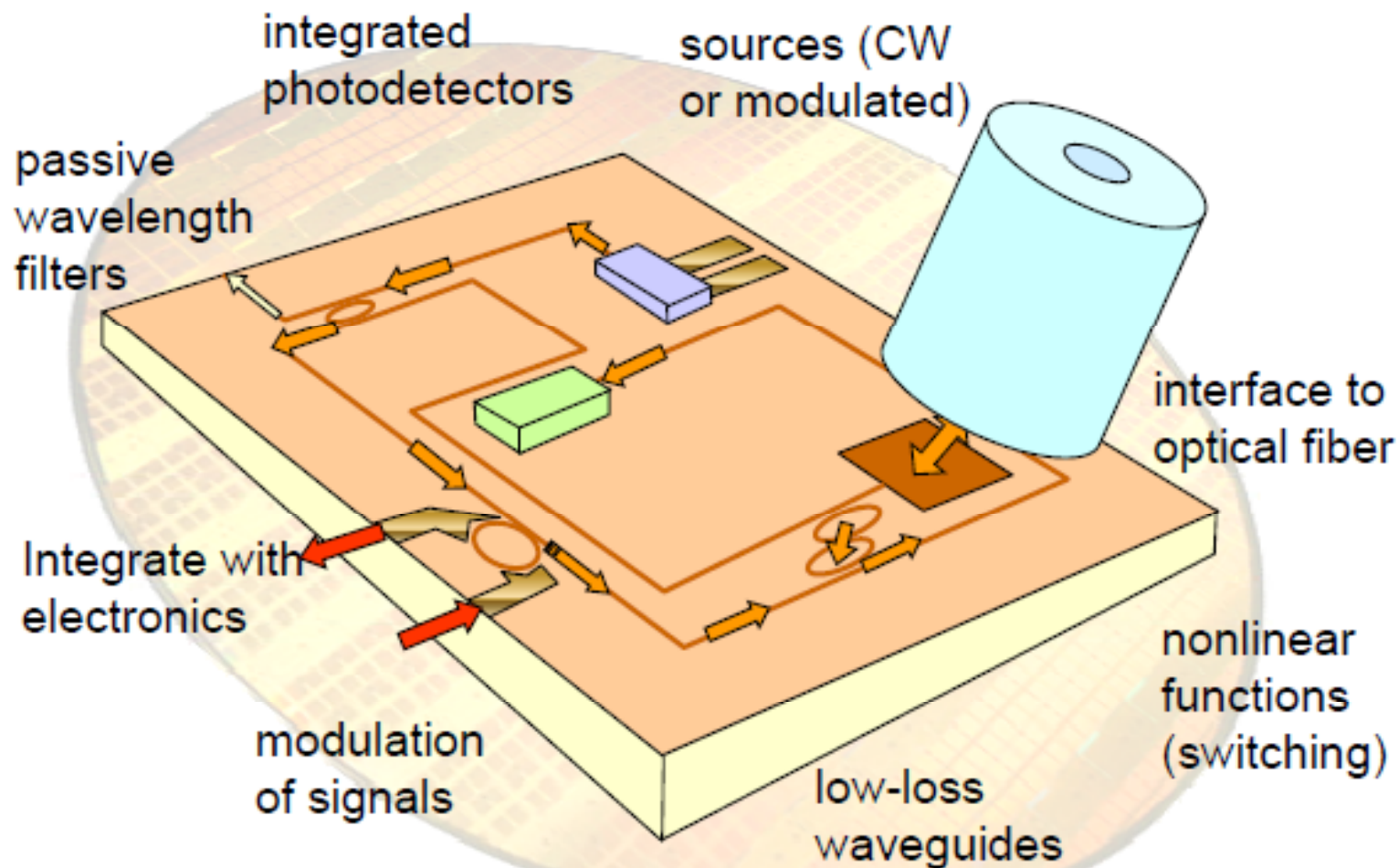
Basic building blocks



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Functions to be integrated



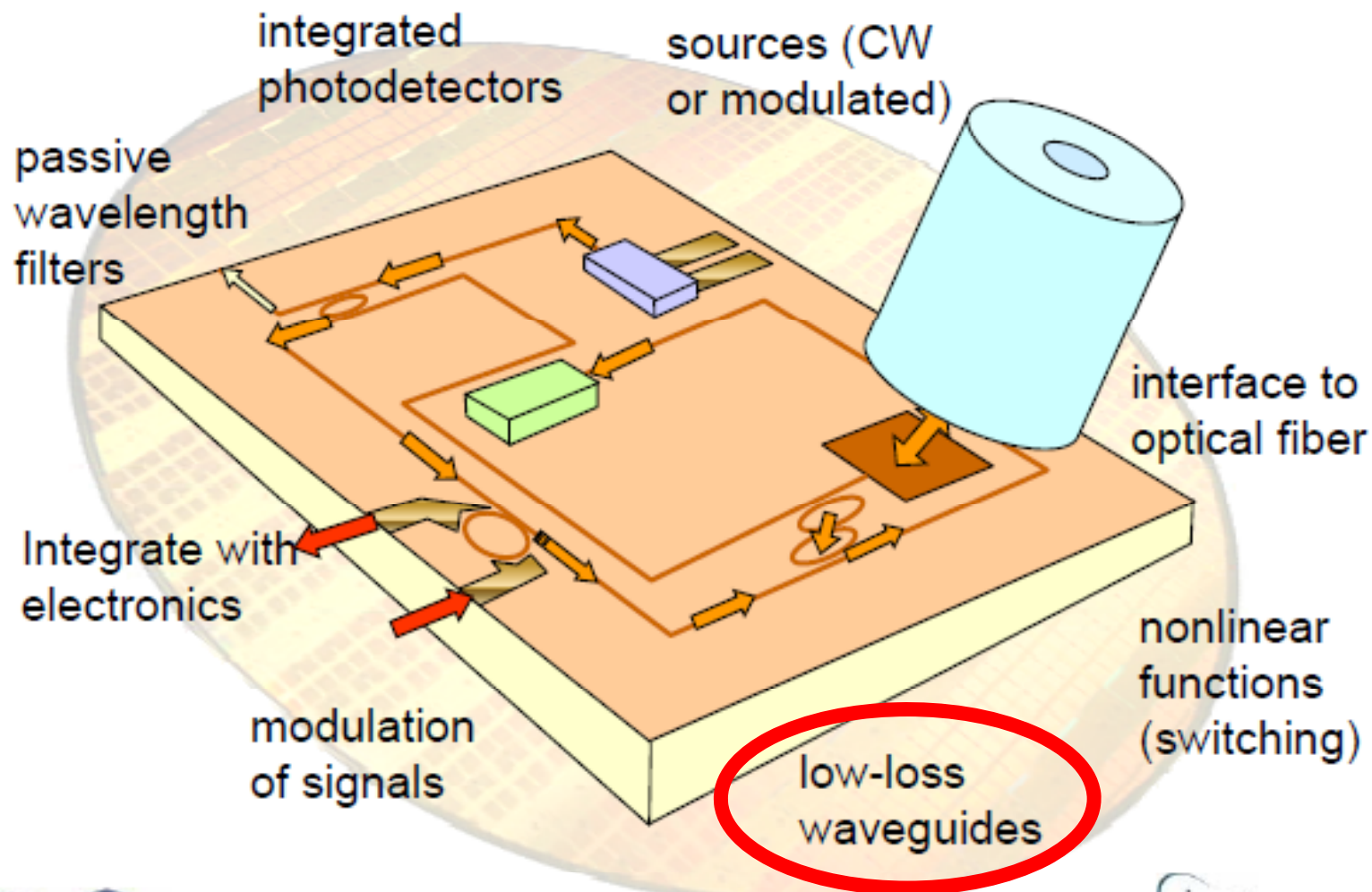
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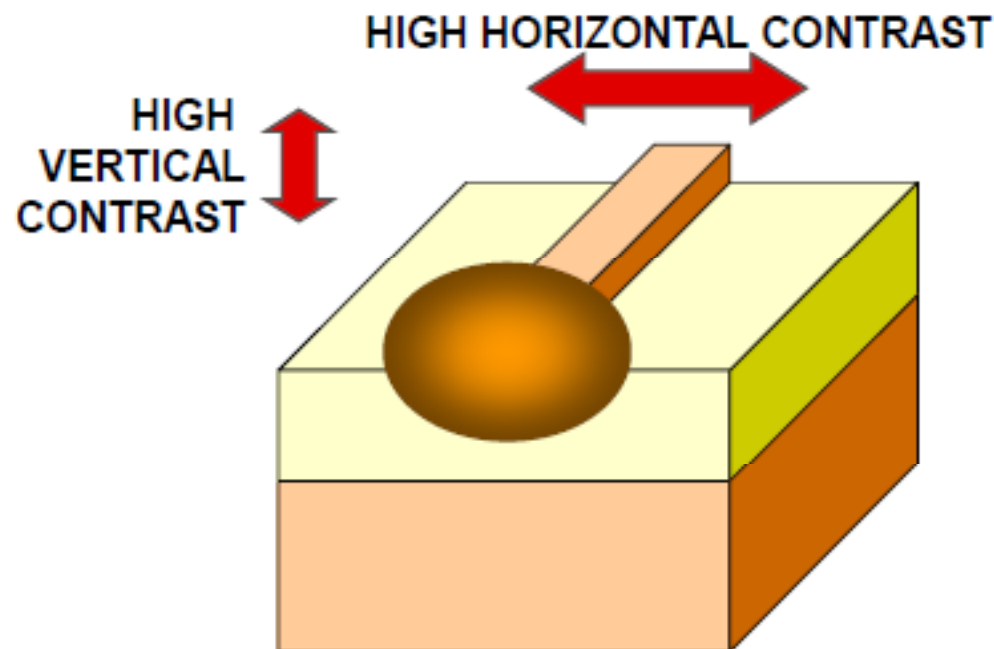
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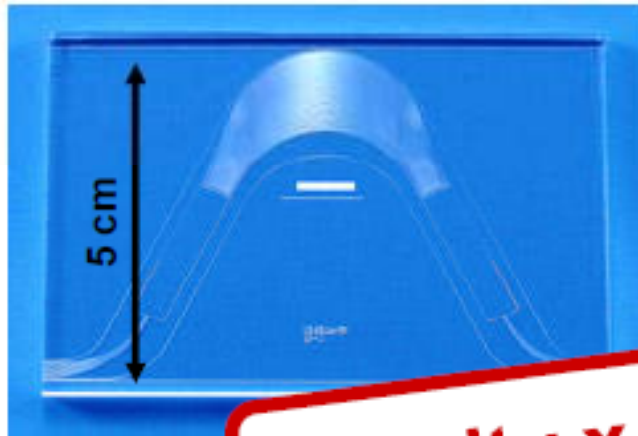
SOI Photonic Wires

High-contrast waveguide

- Large index contrast: 3.45 to 1.45
- Submicron cross section: $450 \times 220\text{nm}^2$
- Sharp bends ($R \sim 2\text{-}3\mu\text{m}$)

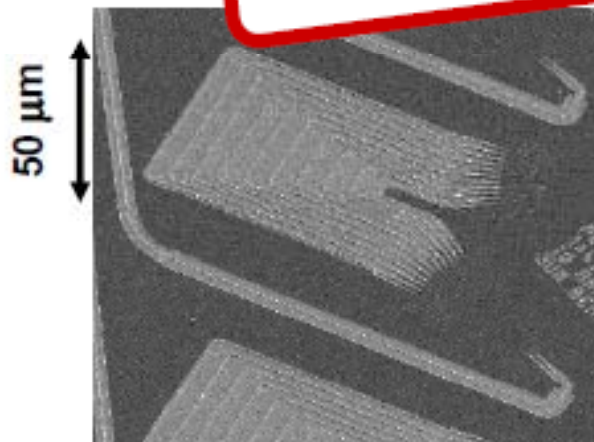


Larger-scale integration

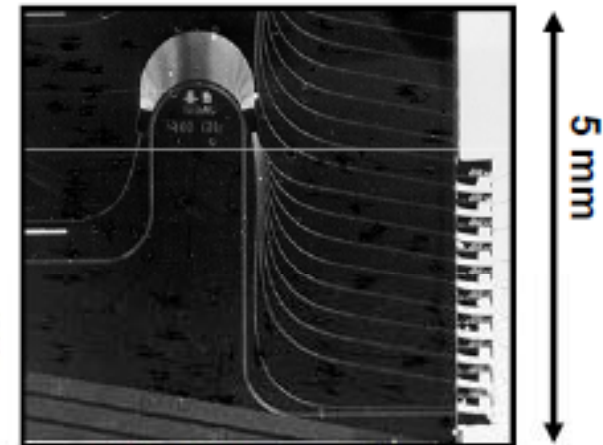


Low Contrast - Fiber Matched
(silica or polymer based)
Bend Radius ~ 5 mm
Size $\sim$ several cm^2

Density $\times 10^6$

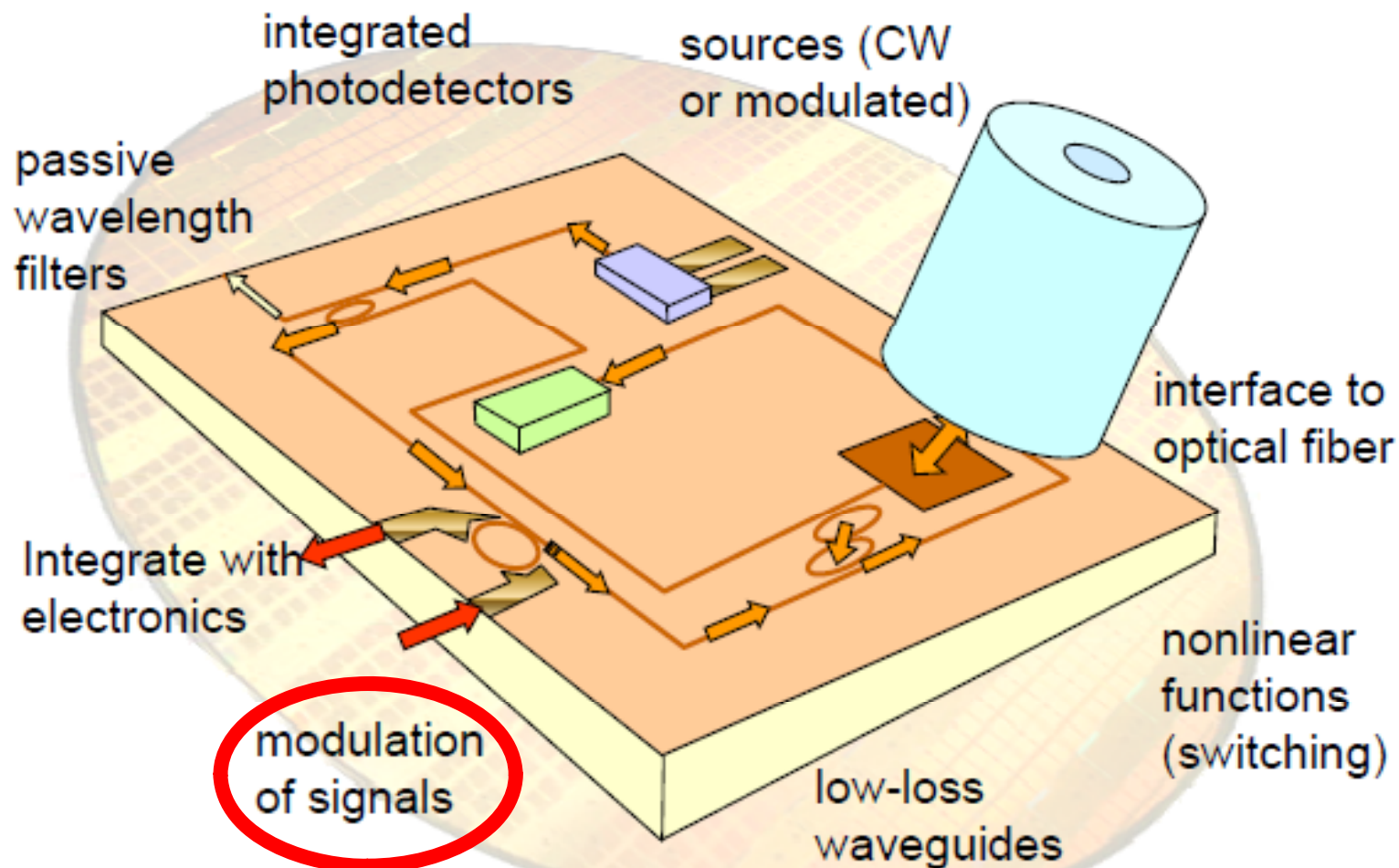


Ultra-high Contrast
(Silicon on Insulator)
Bend Radius $< 5 \mu\text{m}$



Medium Contrast
(InP-InGaAsP)
Bend Radius $\sim 500 \mu\text{m}$

Functions to be integrated



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Modulator

- Because of its crystal structure, silicon is not a useful conventional electro-optic material
- Because of its indirect bandgap, silicon has no near bandgap nonlinearities
- Thermo-optical effect is strong but slow

The only effect that is left is the free carrier or Drude effect

$$\Delta n = - \left[8.8 \times 10^{-22} \Delta N + 8.5 \times 10^{-18} (\Delta P)^{0.8} \right]$$
$$\Delta \alpha = \left[8.5 \times 10^{-18} \Delta N + 6.0 \times 10^{-18} (\Delta P) \right]$$



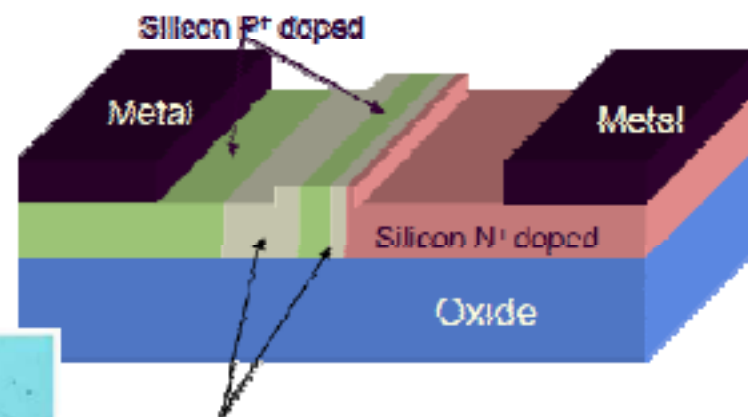
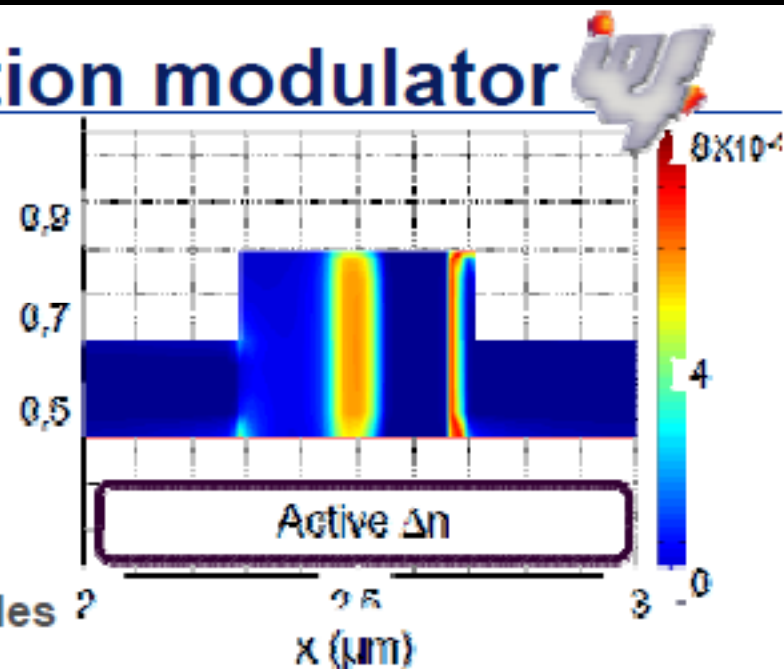
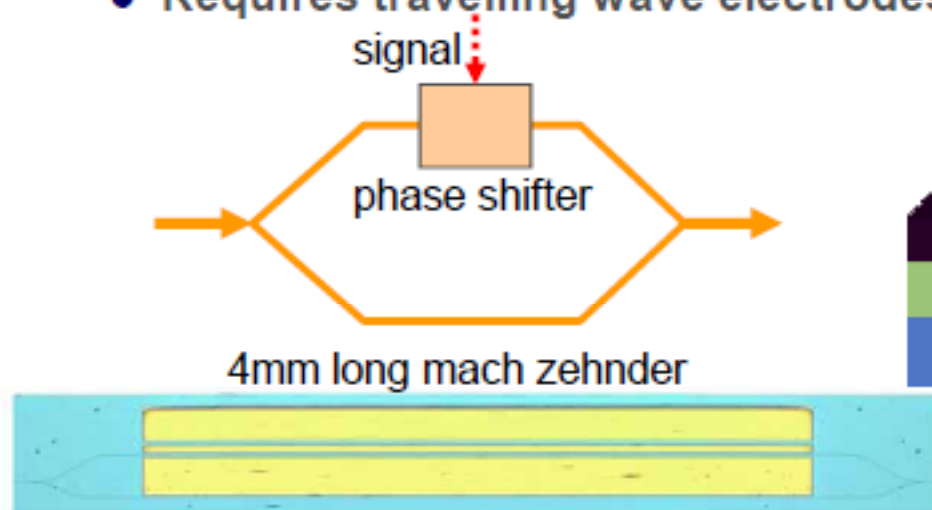
Example: depletion modulator

Complex multi-doping profile

- Larger index change
- Lower RC

But

- Still a long device (4mm)
- Requires travelling wave electrodes



non intentionally-doped Silicon

D. Marris-Morini, OpEx 16 (2008)

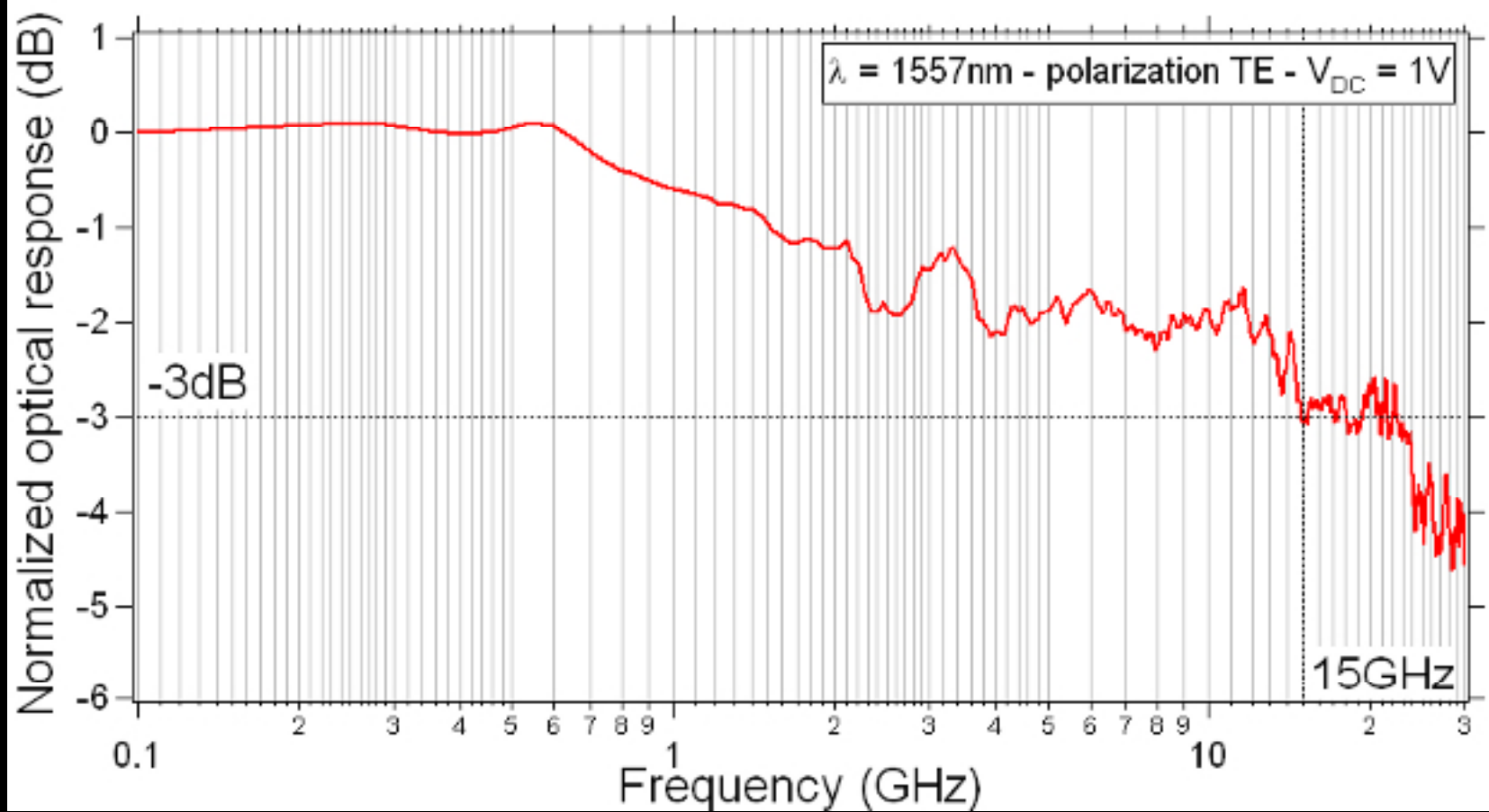


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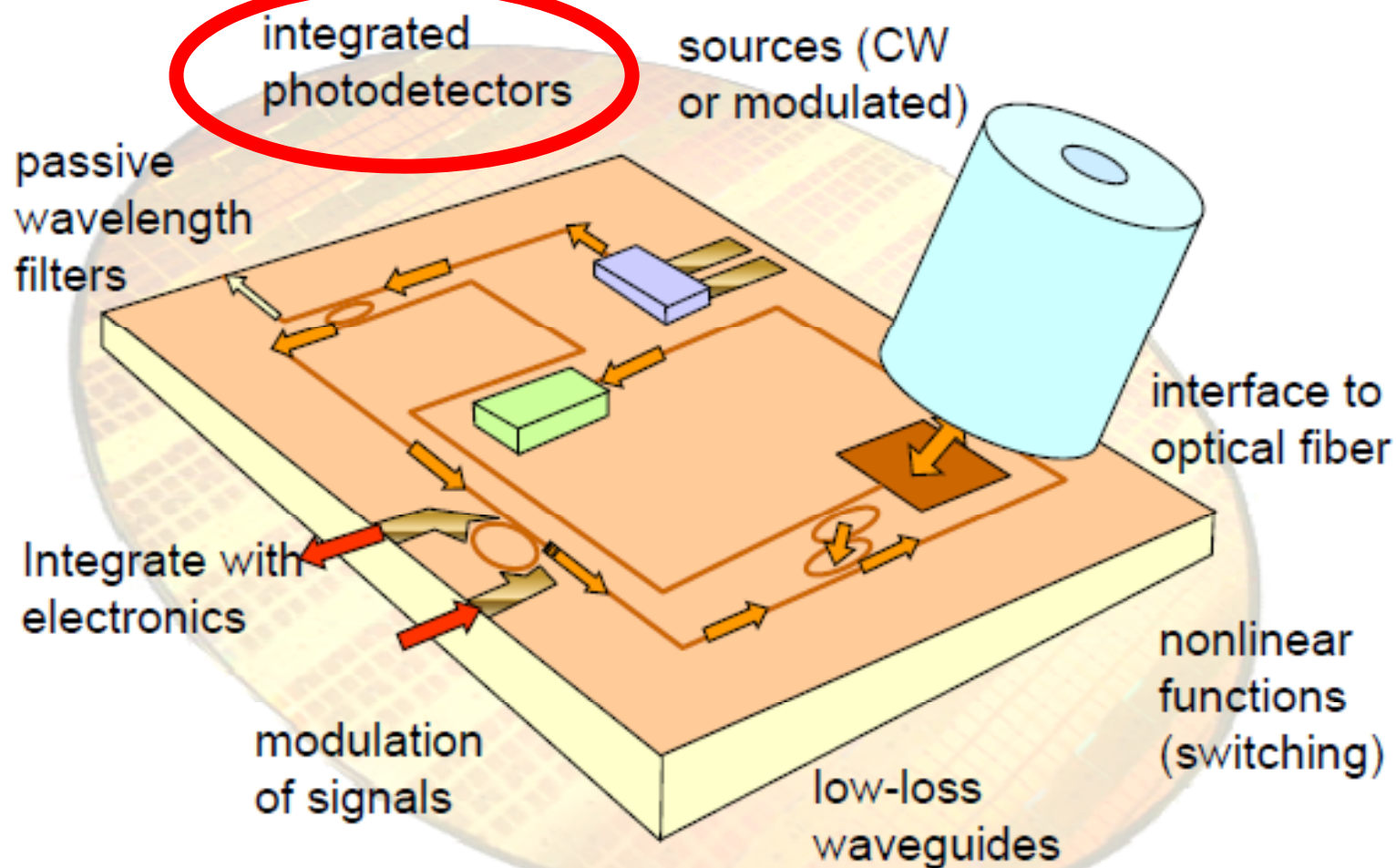


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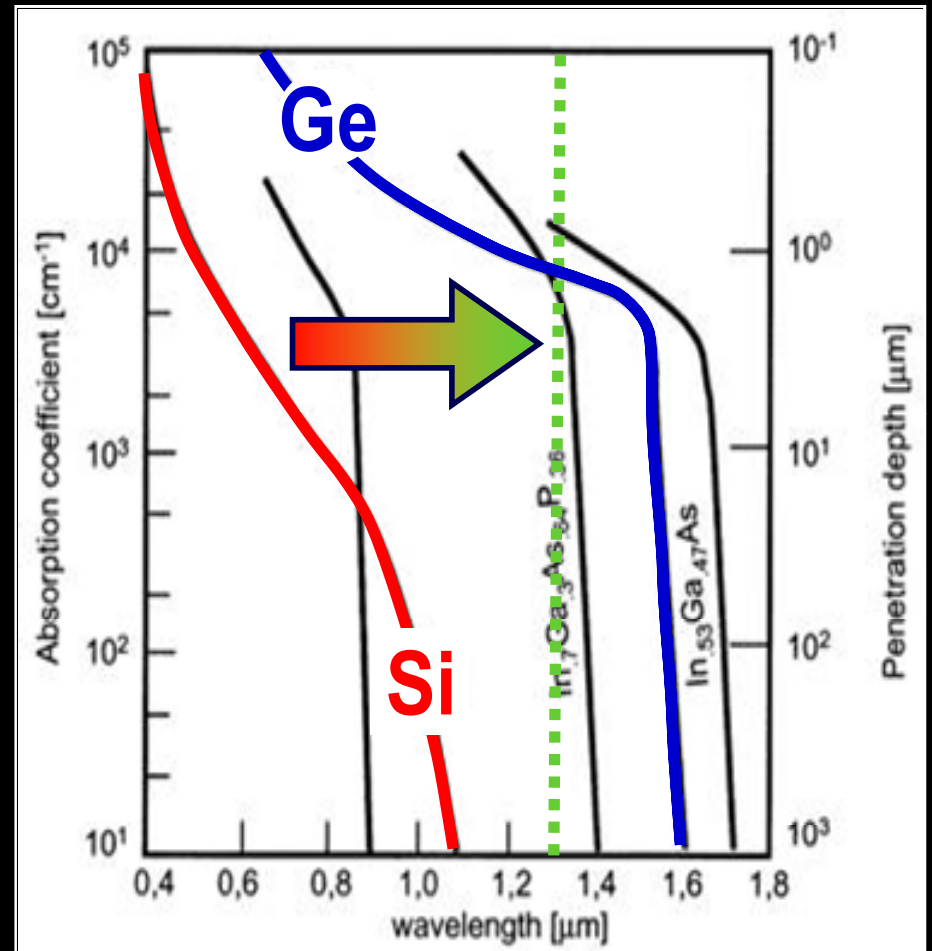


Functions to be integrated

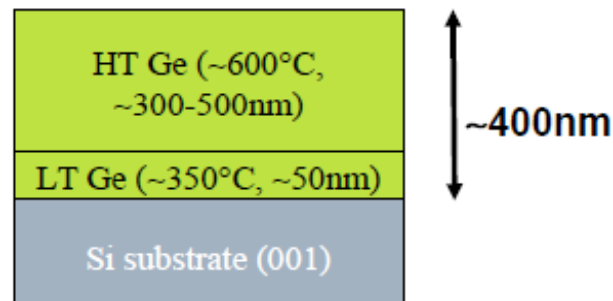


Photodetection

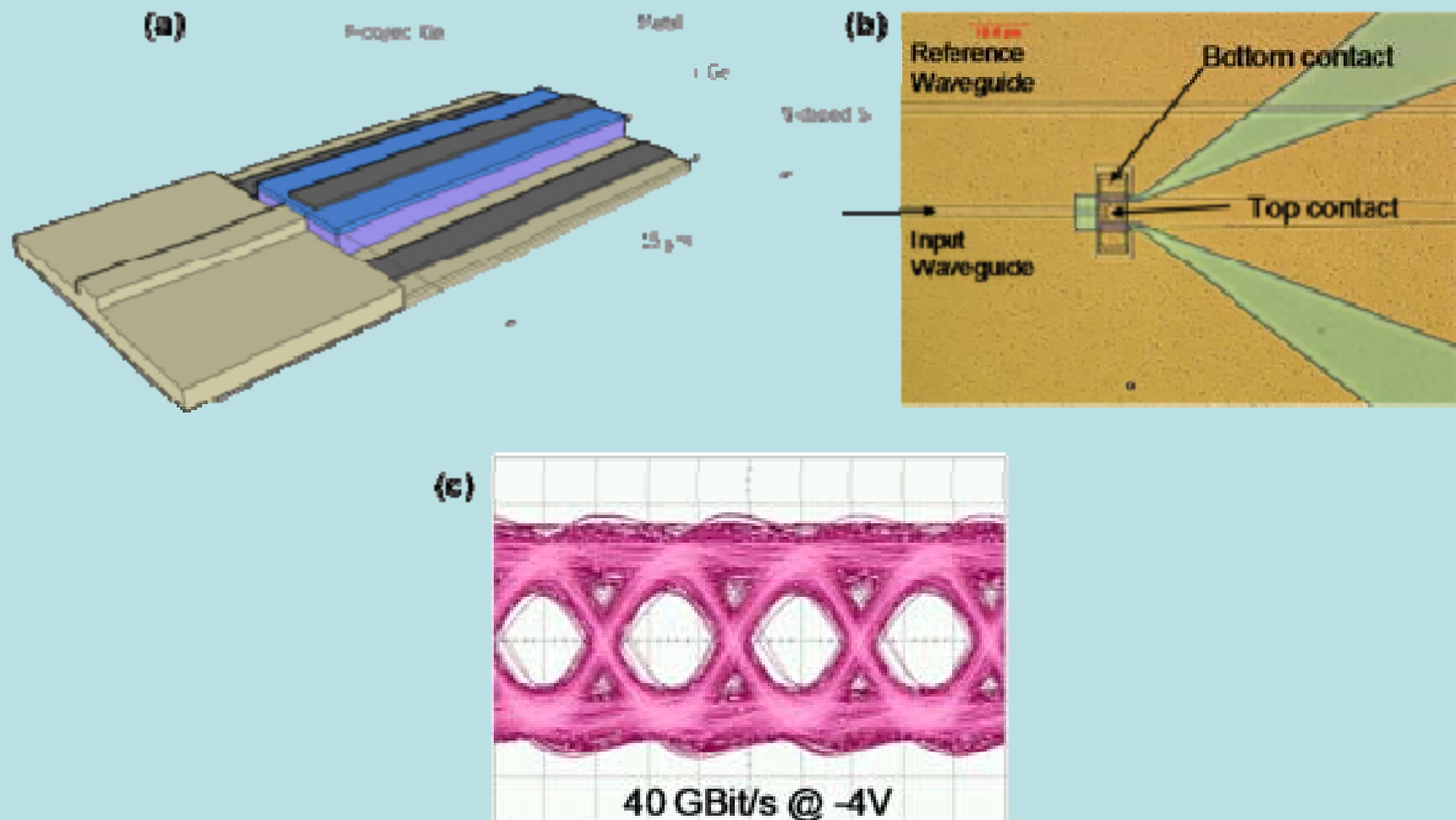
- Silicon does not absorb IR well
 - Use hybrid approach
 - Use SiGe or strained Ge
 - Use damaged silicon



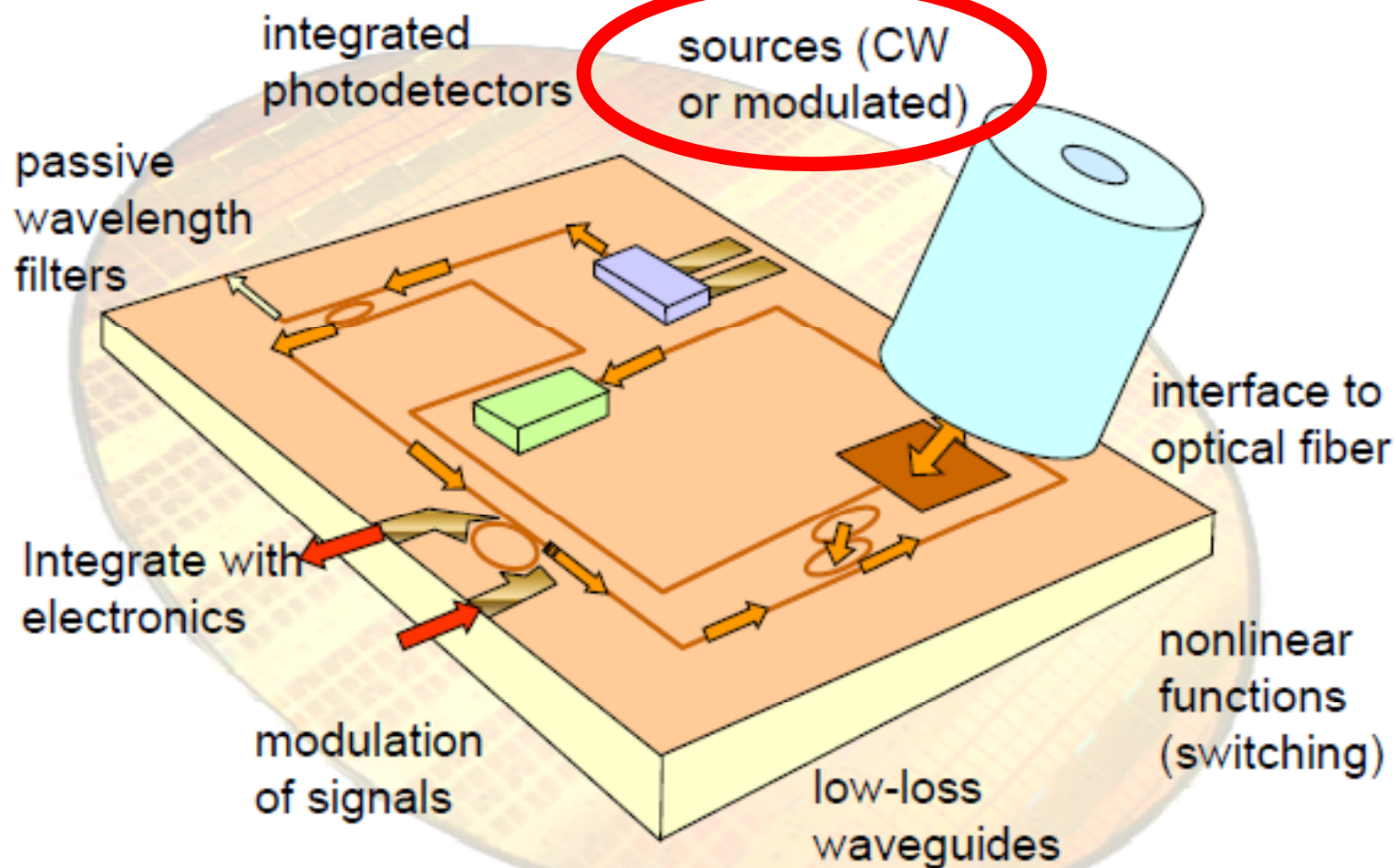
- Two-step growth process:
 - Direct growth of Ge on Si using a low temperature ($\sim 350^\circ$) CVD process
 - $\Rightarrow$ thin (a few 10nm) highly-dislocated Ge layer
 - Growth of a thick Ge layer (a few 100nm) at a higher temperature ($\sim 600^\circ$)
 - $\Rightarrow$ high quality Ge absorbing layer
- Thermal annealing to reduce the dislocation density



Ge photodetector



Functions to be integrated



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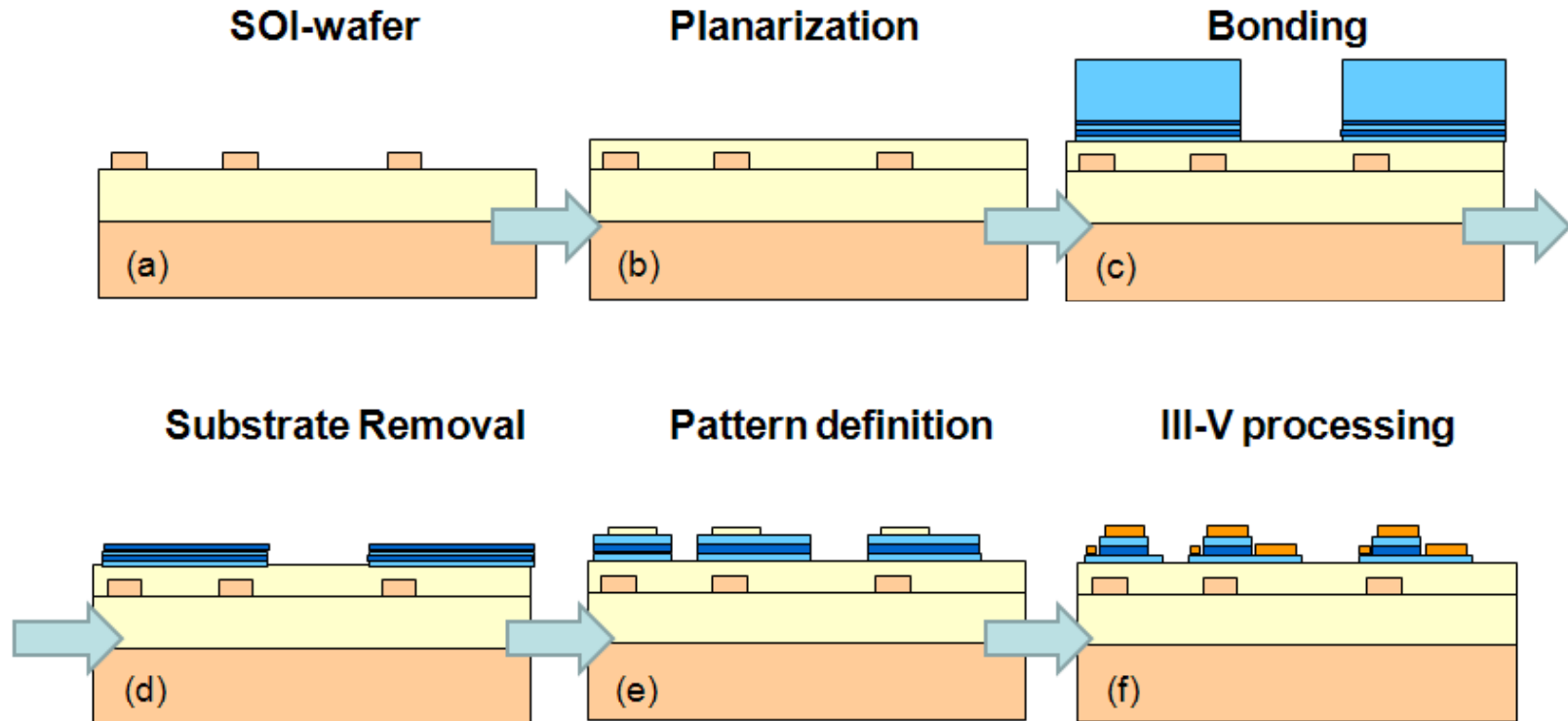


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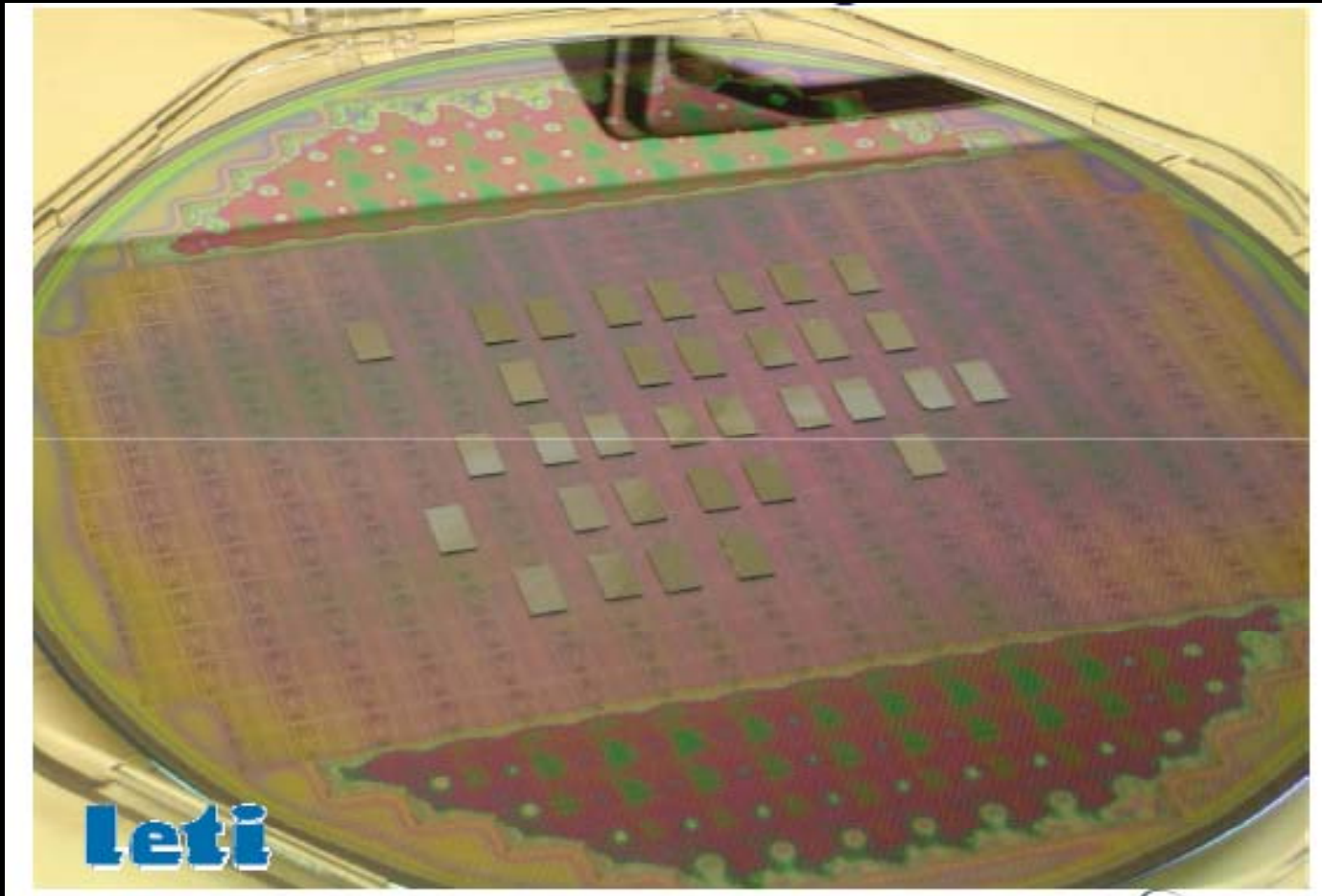


III-V heterogeneous integration for the laser source

Integration Scheme



III-V heterointegration for the laser source

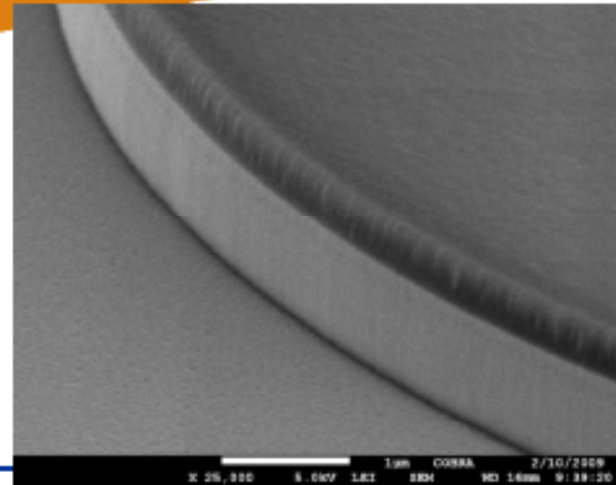
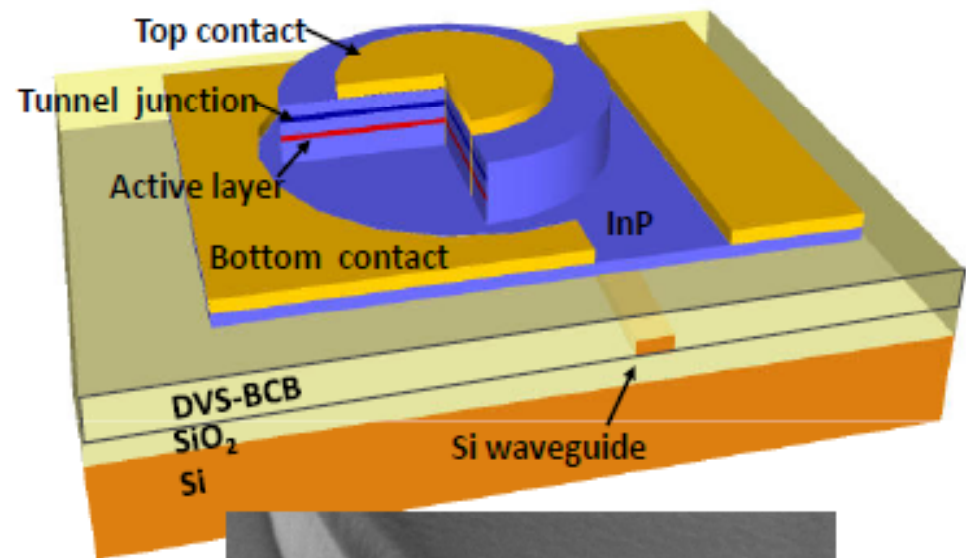


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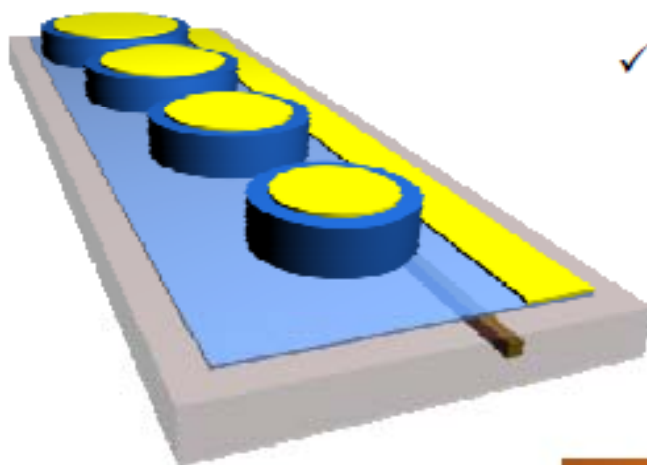


InP microdisk laser

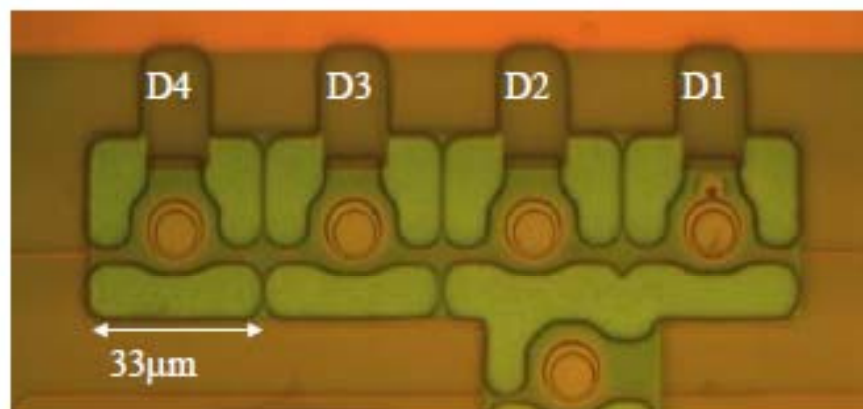
- 7.5 μm diameter
- 600 nm height
- Adhesive bonding
(BCB ~ 250 nm)
- Evanescent coupling
to Si Waveguide



Multi-wavelength Laser



- ✓ Several (4) microdisks with different diameters are cascaded on one bus SOI waveguide.



J. Van Campenhout, L. Liu, et al, PTL 20, 1345, (2008).

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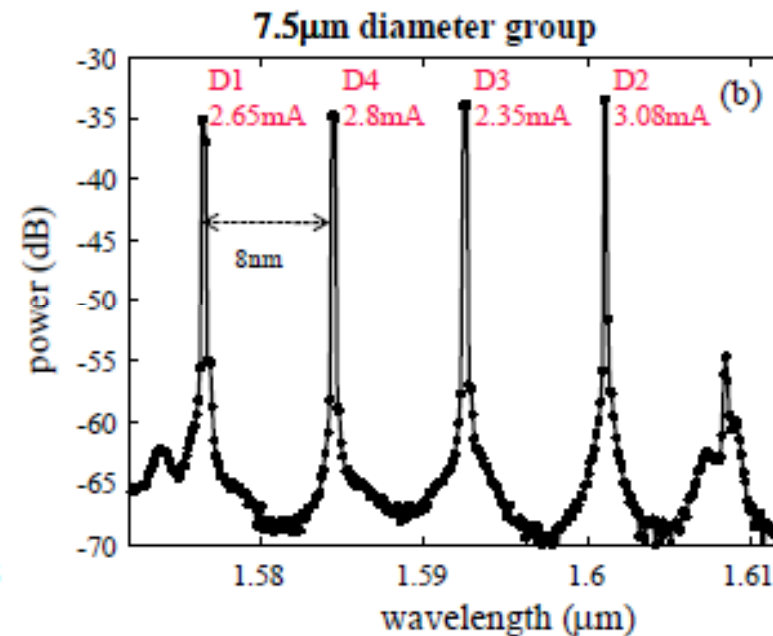
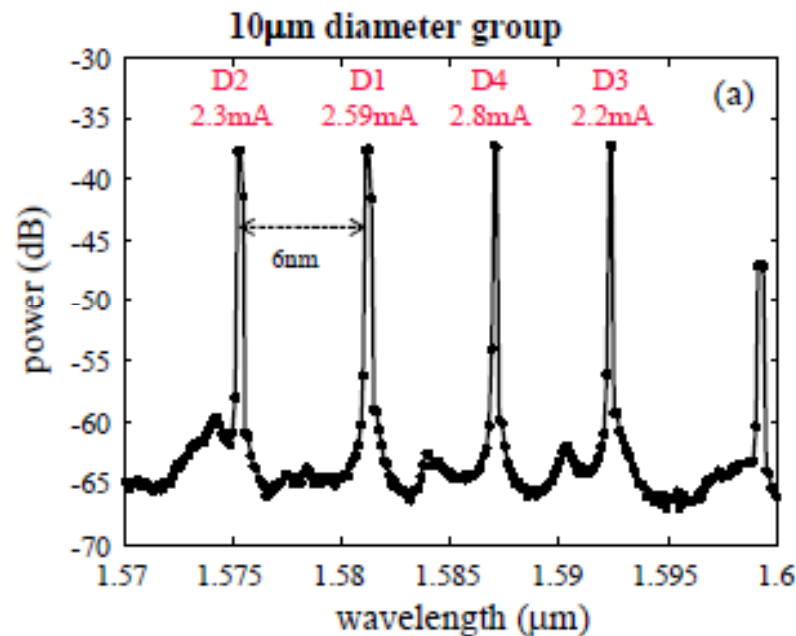
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Multi-wavelength Laser



- Uniform peak power was obtained by adjusting the driving current of each individual disk laser.



J. Van Campenhout, L. Liu, et al, PTL 20, 1345, (2008).

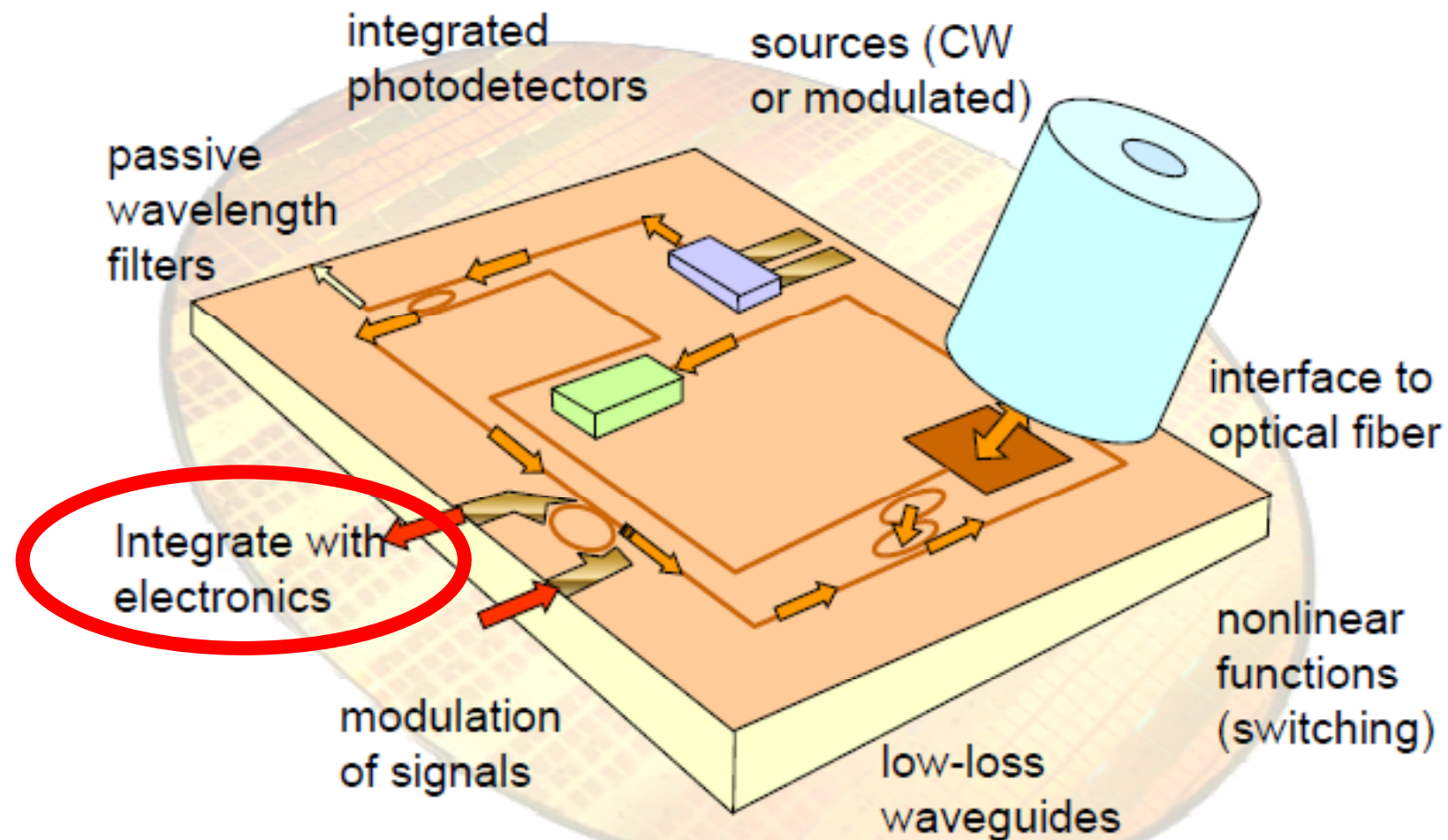
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Functions to be integrated



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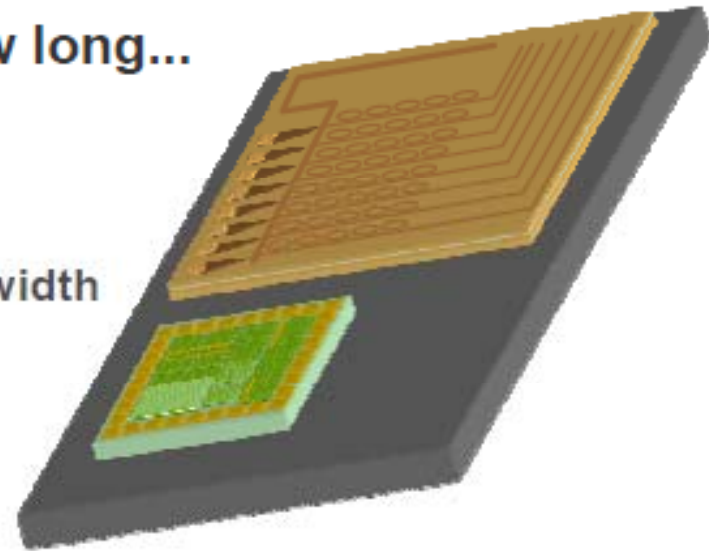
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Co-packaging?

Works for now, but for how long...

- limited integration density
 - edge vs. area
- long distance = lower bandwidth



Integrate photonics with CMOS
in a more scalable way



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Where should we integrate the photonics layer ?

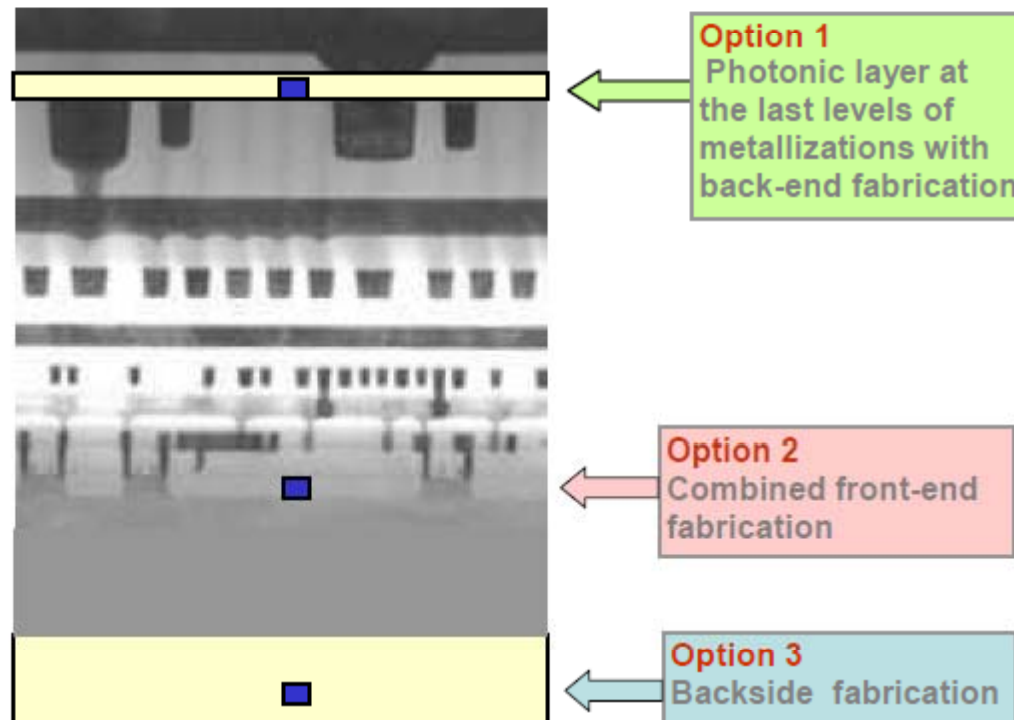
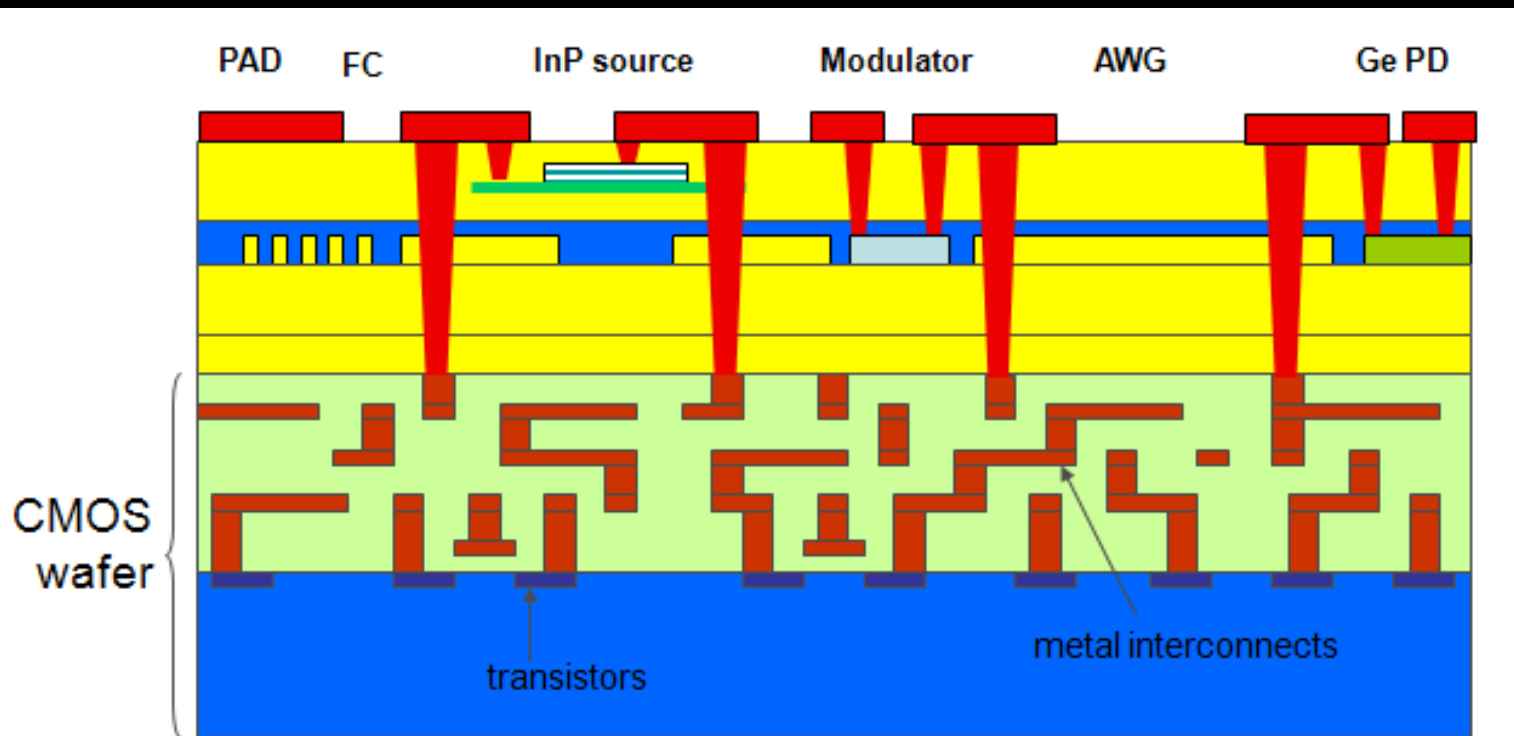


Figure 1: Different options for integrating the photonic layer addressed by the Helios project

Options 1



Silicon Photonics – PhD course prepared within FP7-224312 Helios project



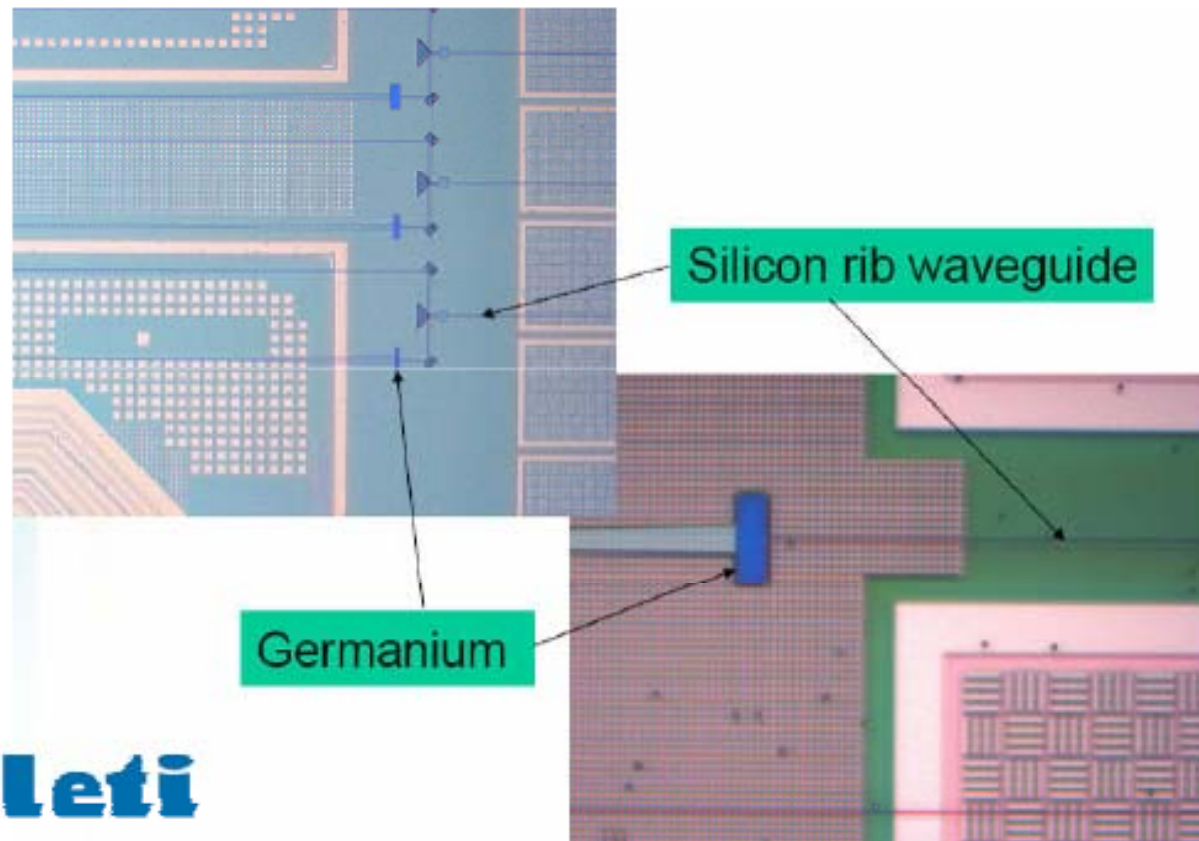
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Options 1

CMOS + Photonics wafer bonding

Photonics wafer on top of CMOS wafer



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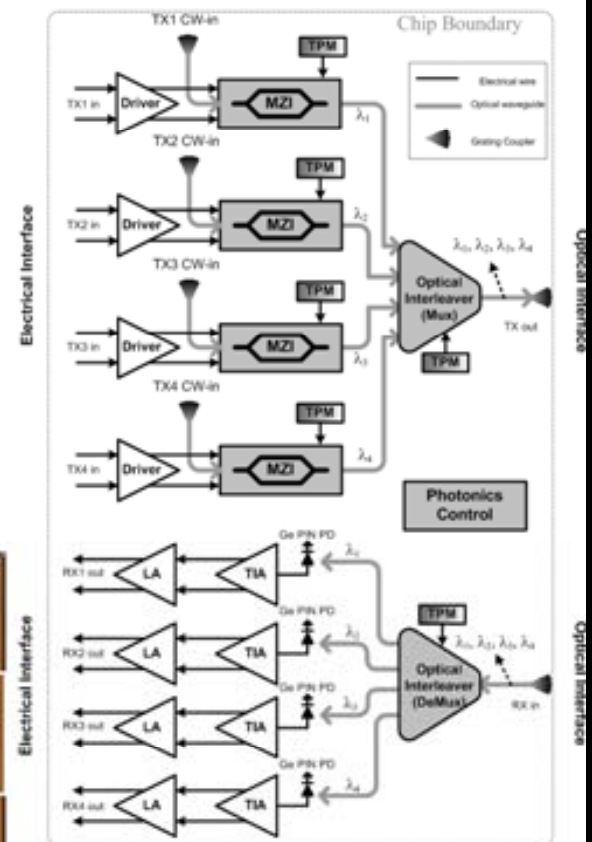
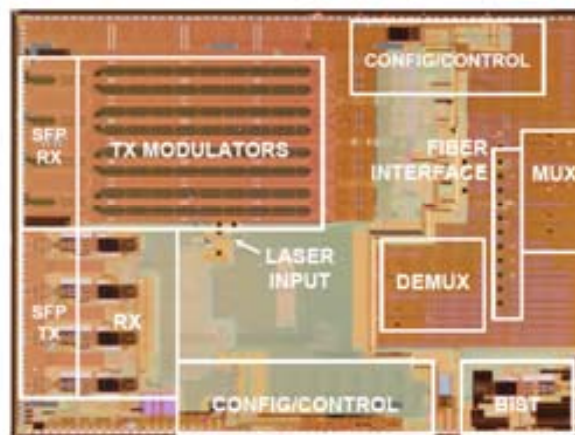
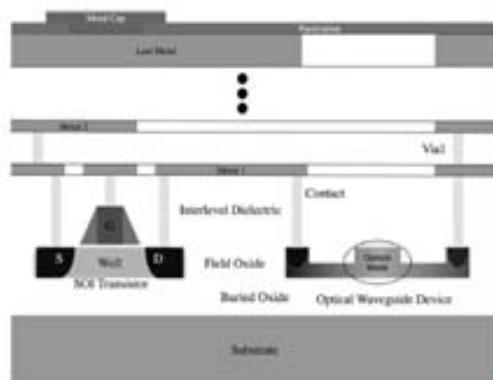
J.M. Fedeli et al. Proc. SPIE 6125 (2006)

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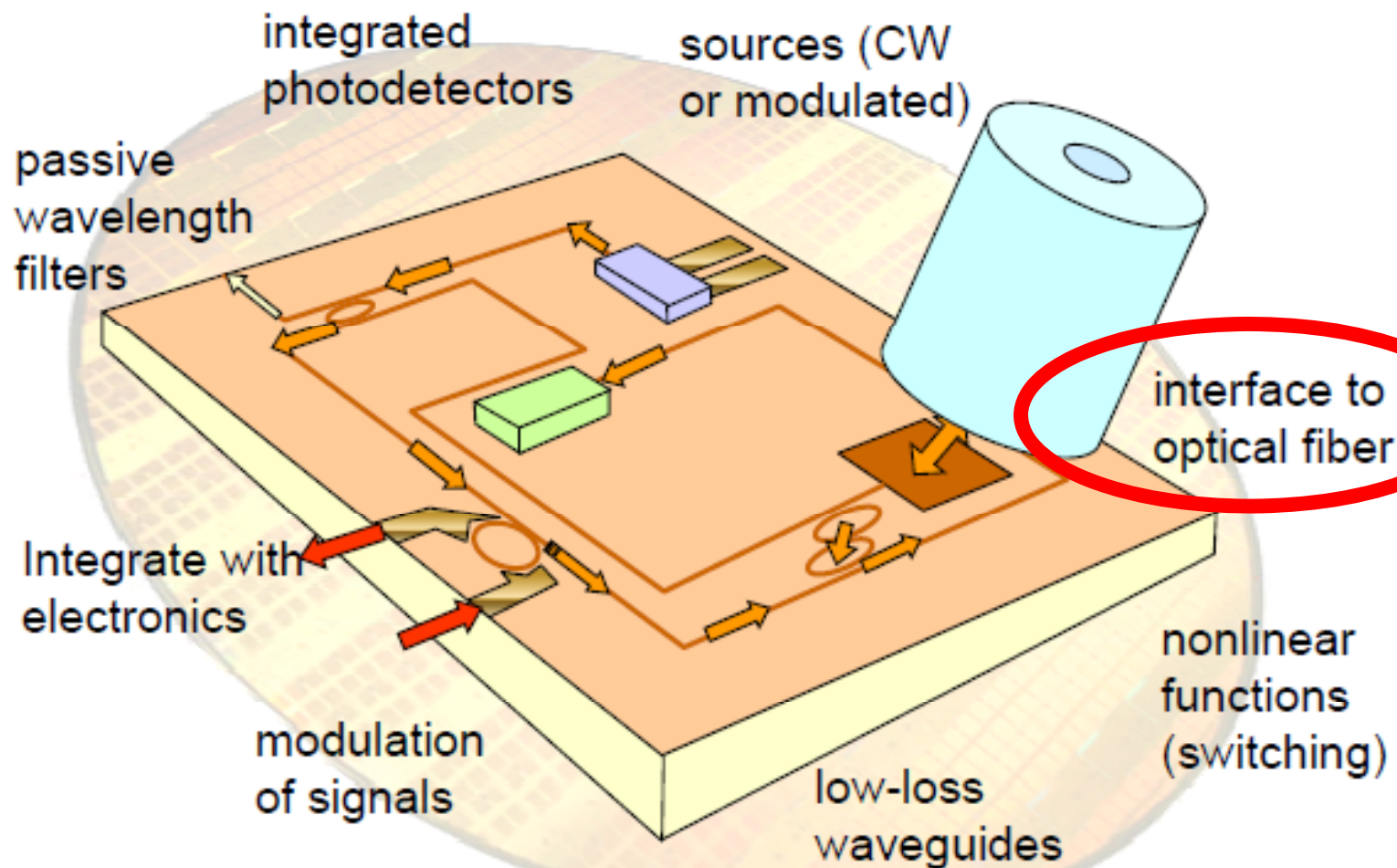


Option 2: Luxtera approach

- Proprietary SOI CMOS 130nm technology
- Proprietary library for IC design
- Flip chip bonded lasers or external WDM lasers
- Surface gratings fiber couplers
- MUX and DEMUX with controlled MMI
- 10Gb/s modulator based on lateral Si depletion
- 20GHz Ge photodetectors
- Electronic control of optical devices



Functions to be integrated



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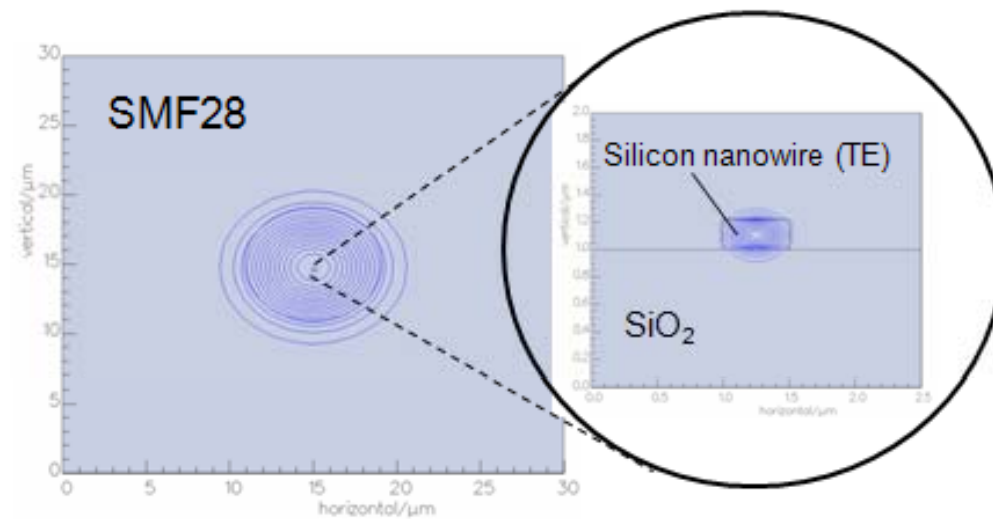
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Major obstacle in silicon photonics

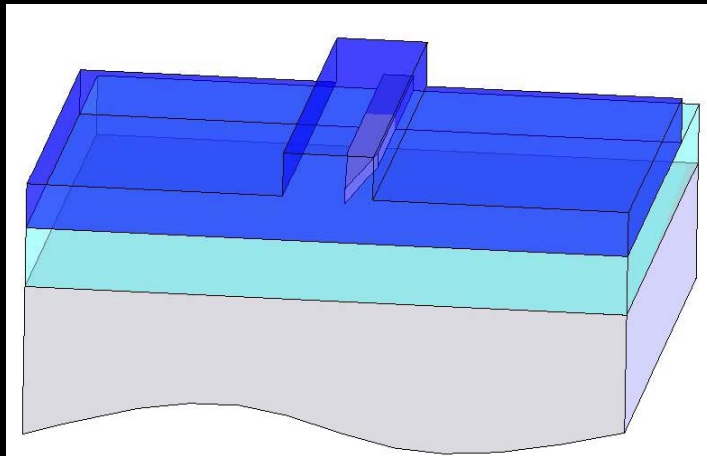
MFD of fiber and waveguides do not match



This requires

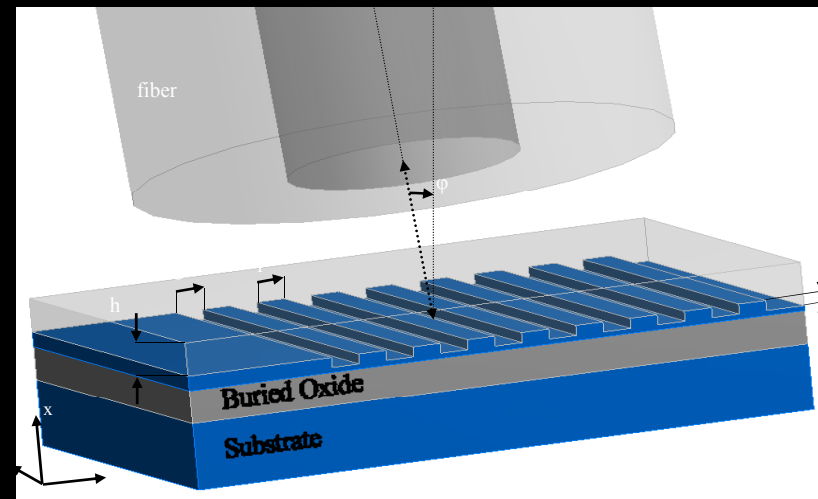
Spotsize conversion structures

Lateral coupling



- typically based on inverted tapers
- spotsize: $\sim 3 \mu\text{m}$

Vertical coupling



- typically based on gratings
- spotsize: $\sim 10 \mu\text{m}$

Example - g-Pack




Fraunhofer
Institut
Zuverlässigkeit und
Mikrointegration

 
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GENT


University
of
St Andrews



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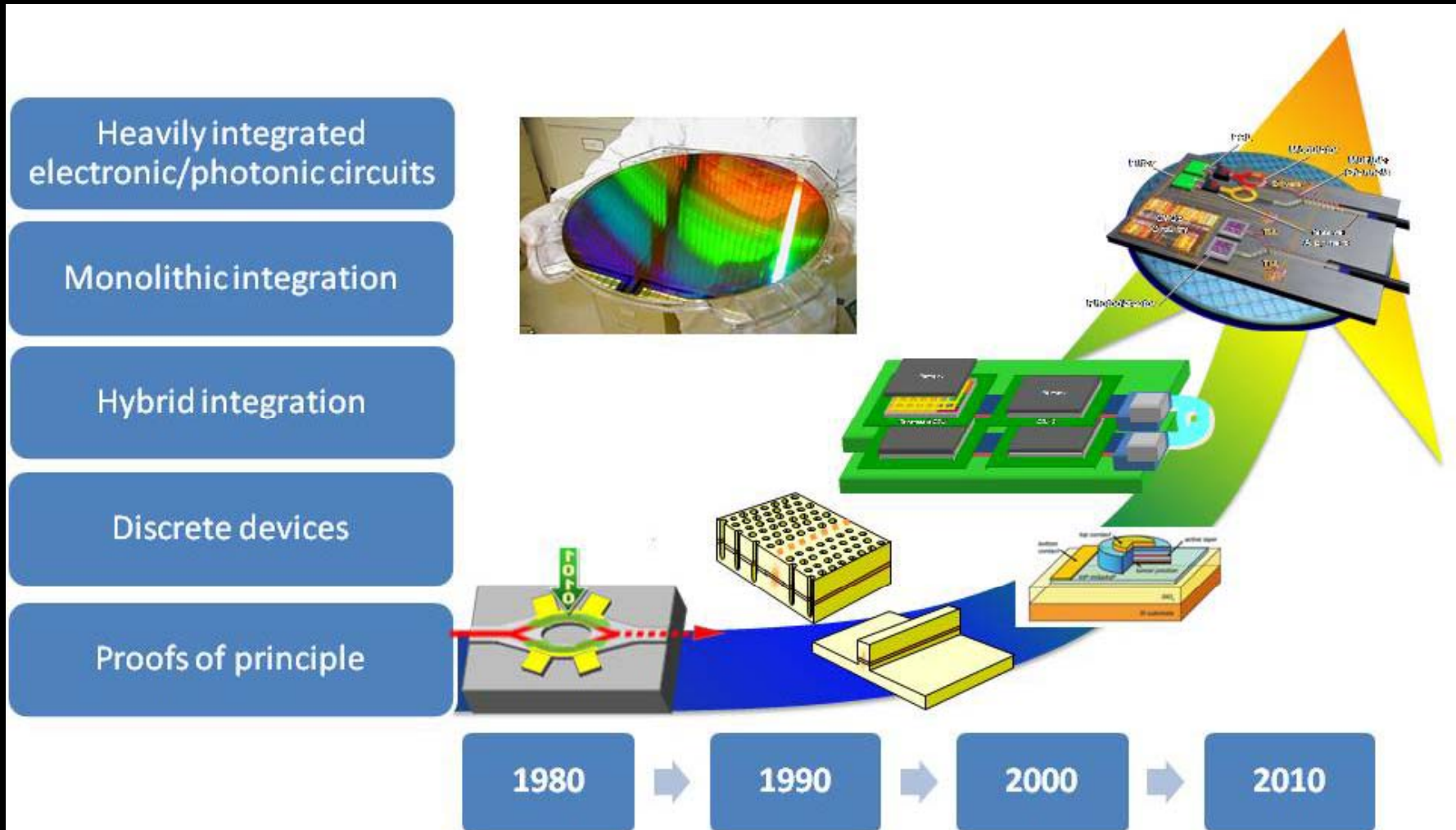


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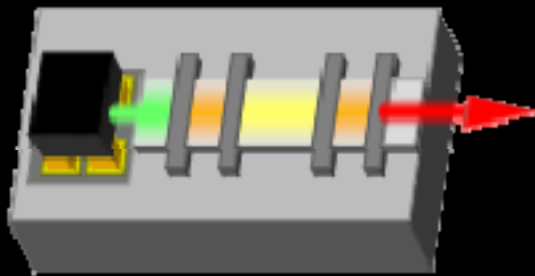


Explosion of silicon photonics

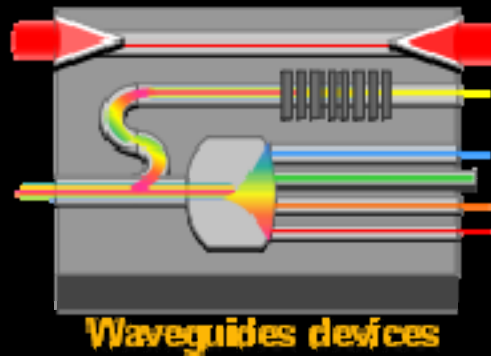


From Building Block Research

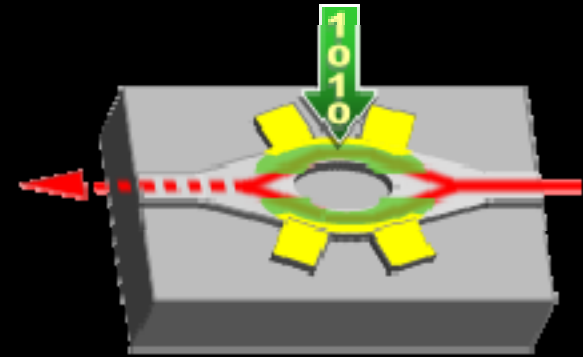
1) Light Source



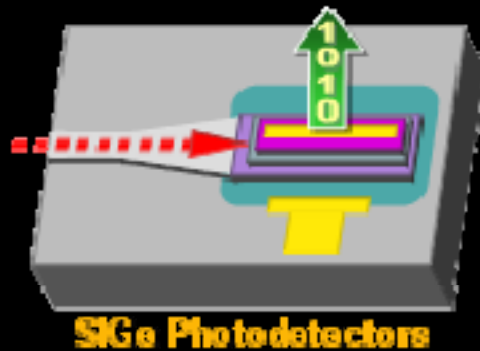
2) Guide Light



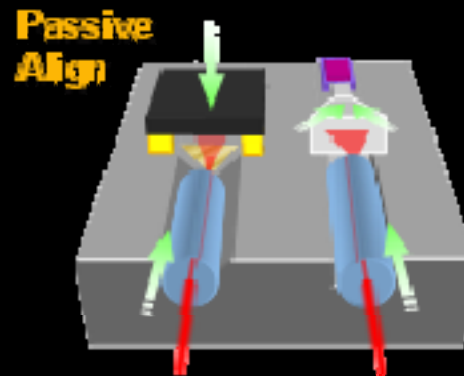
3) Modulation



4) Photo-detection



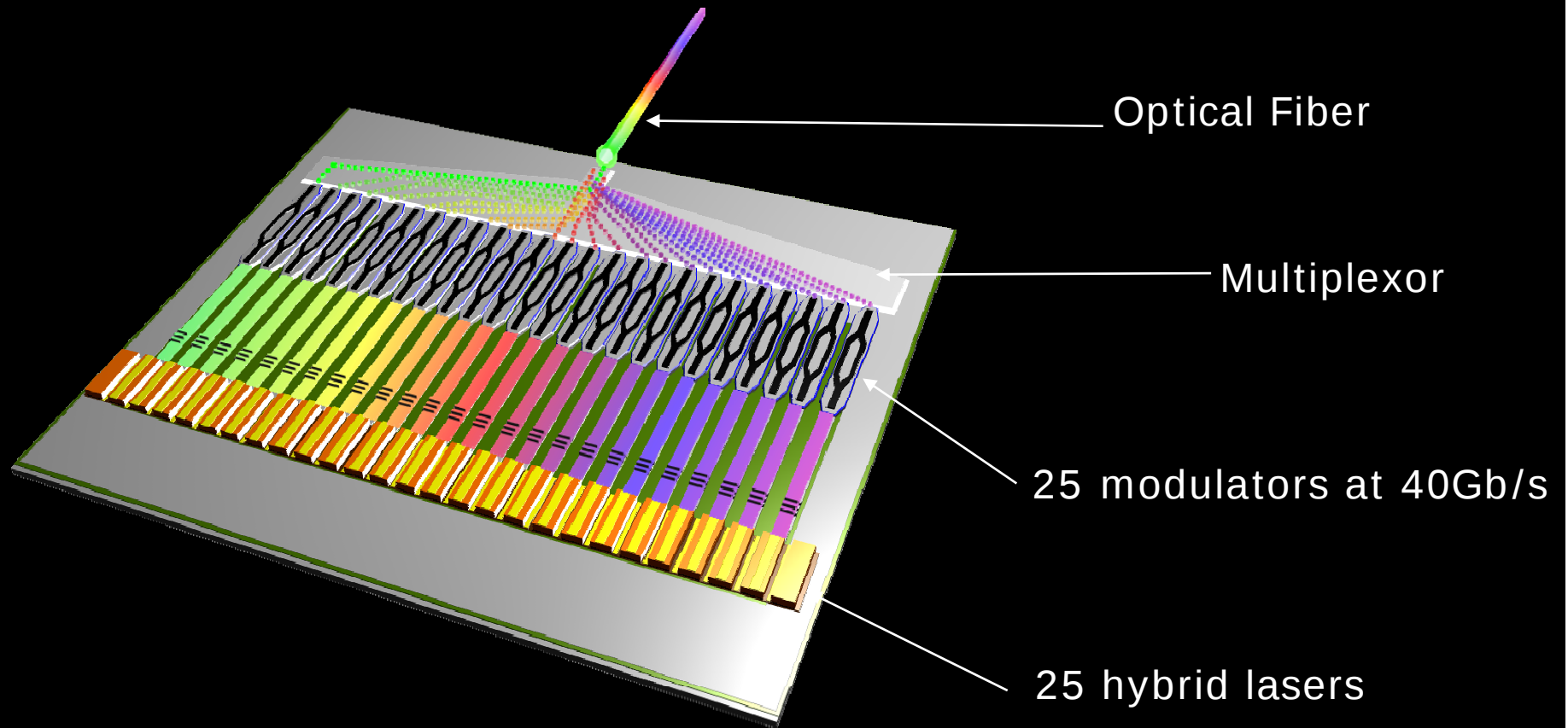
5) Low Cost Assembly



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To Large scale integration

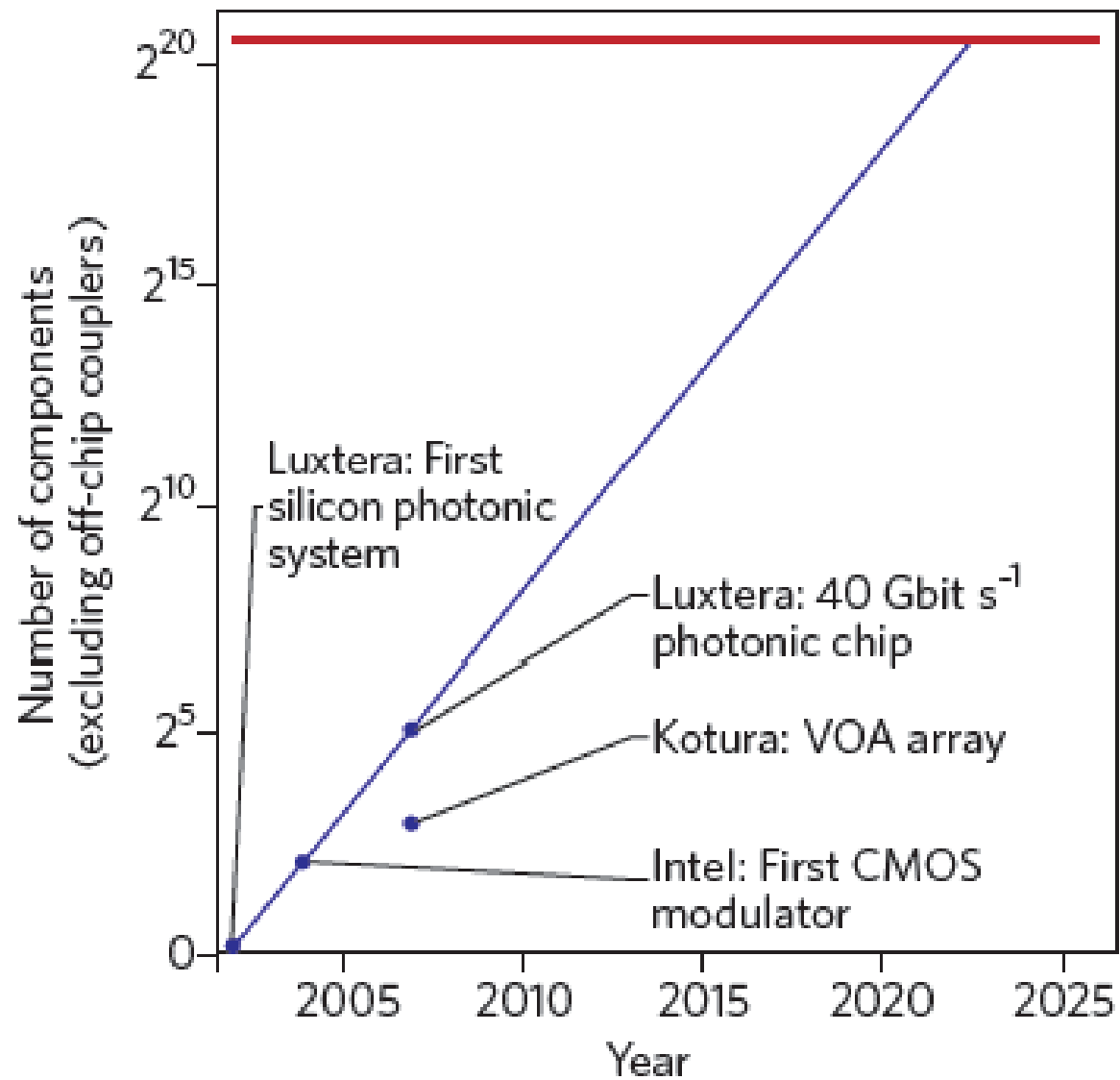


A future integrated 1 Tb/s optical link
on a single silicon chip



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ALEXANDER SPOTT / UNIVERSITY OF WASHINGTON

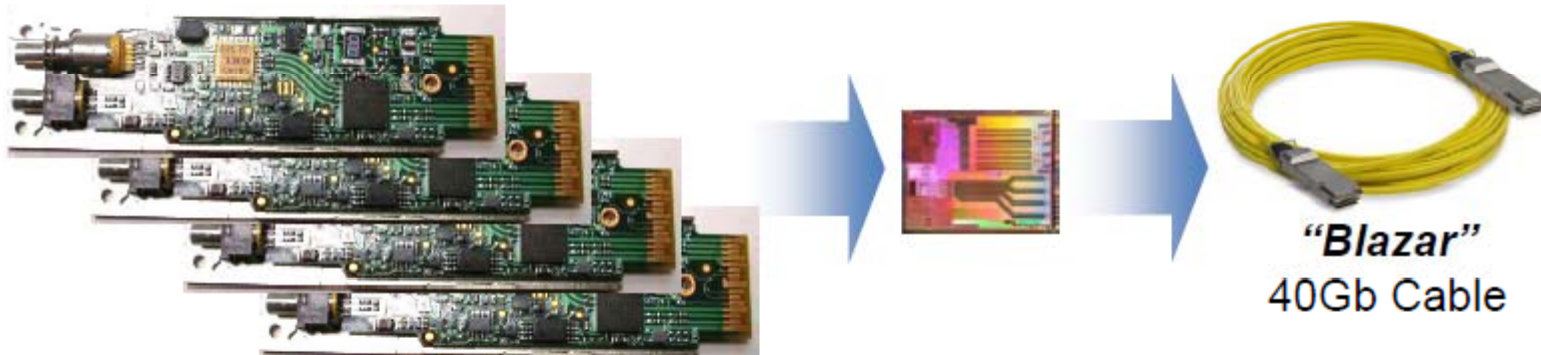


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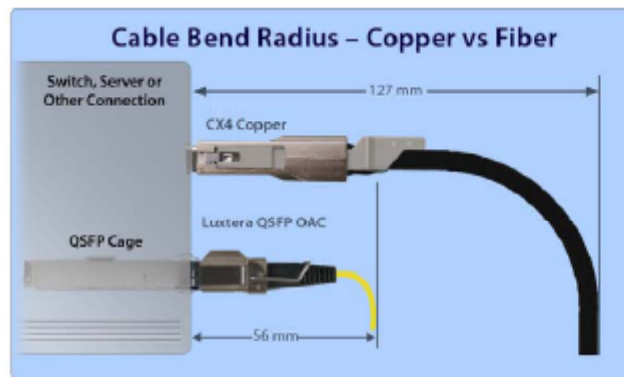


CMOS Photonics Commercialization at Luxtera

Functionality of Four SFP+ 10Gb Transceivers on a single CMOS Die



Optics is now price-competitive with copper!

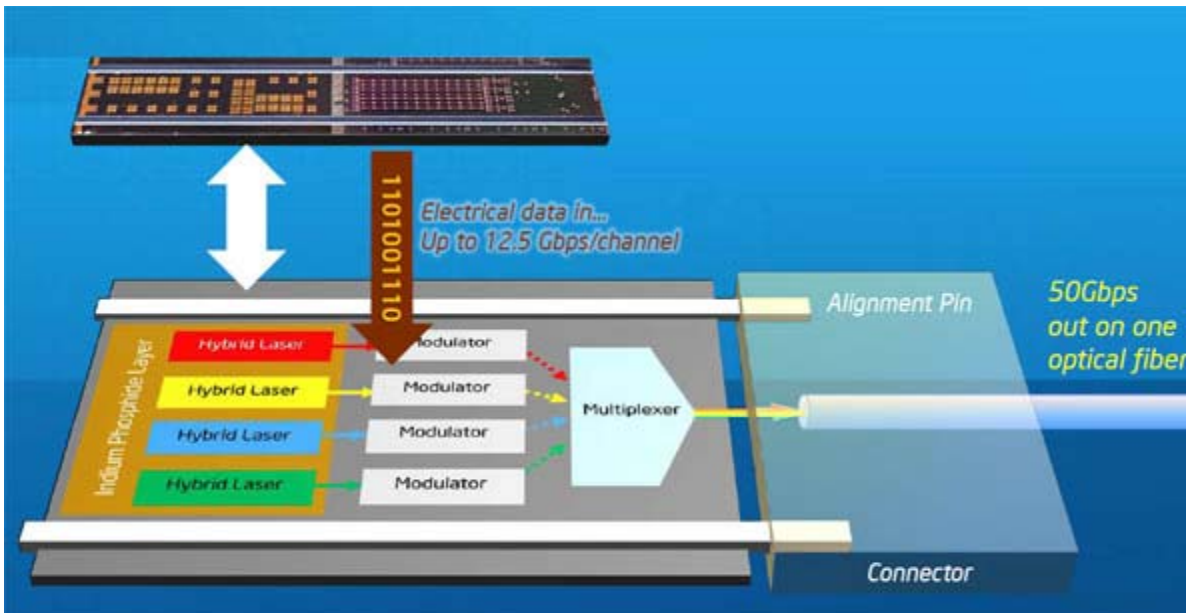


Benefits of optics maintained:

- 20% higher density
- 40% smaller bend radius
- 85% lighter cable
- 600% longer reach



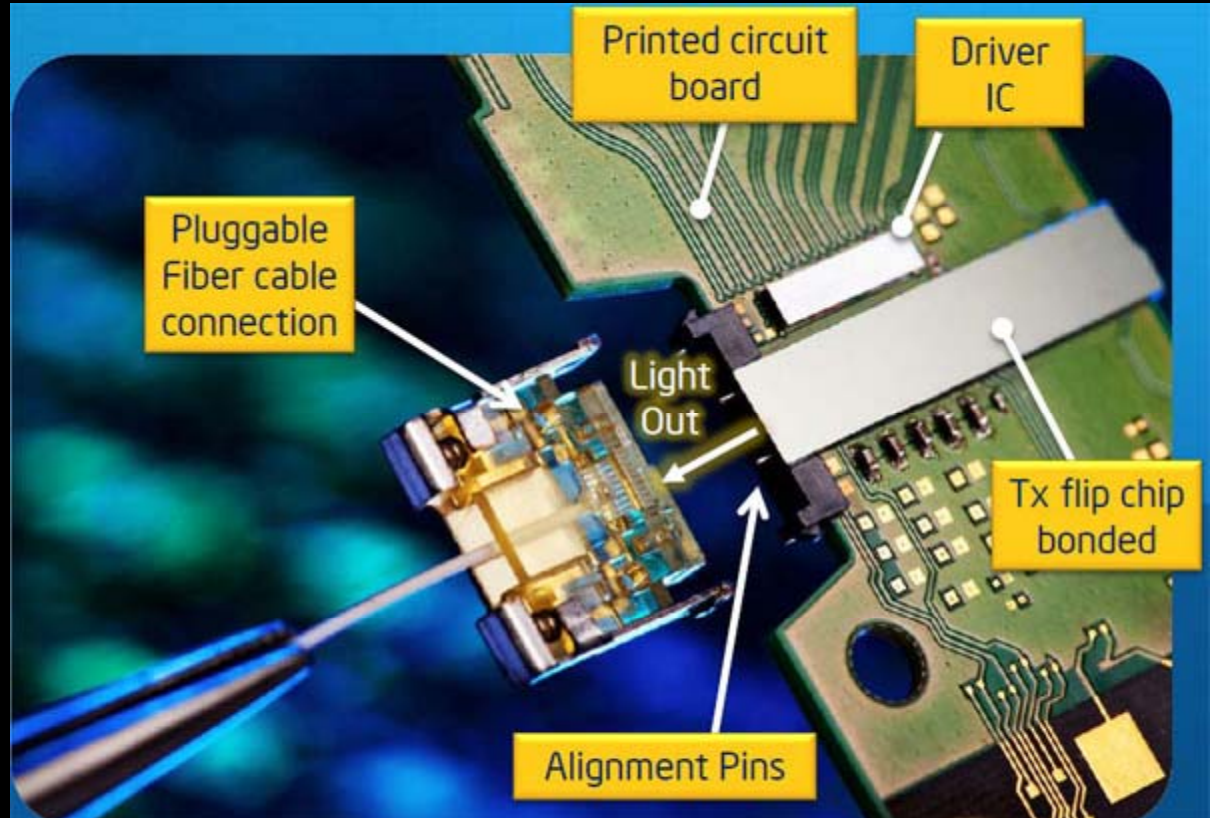
Proprietary & Confidential



Silicon Photonic Link
50Gbps
Multichip approach
Driver 45 nm CMOS
Photonic 90 nm CMOS



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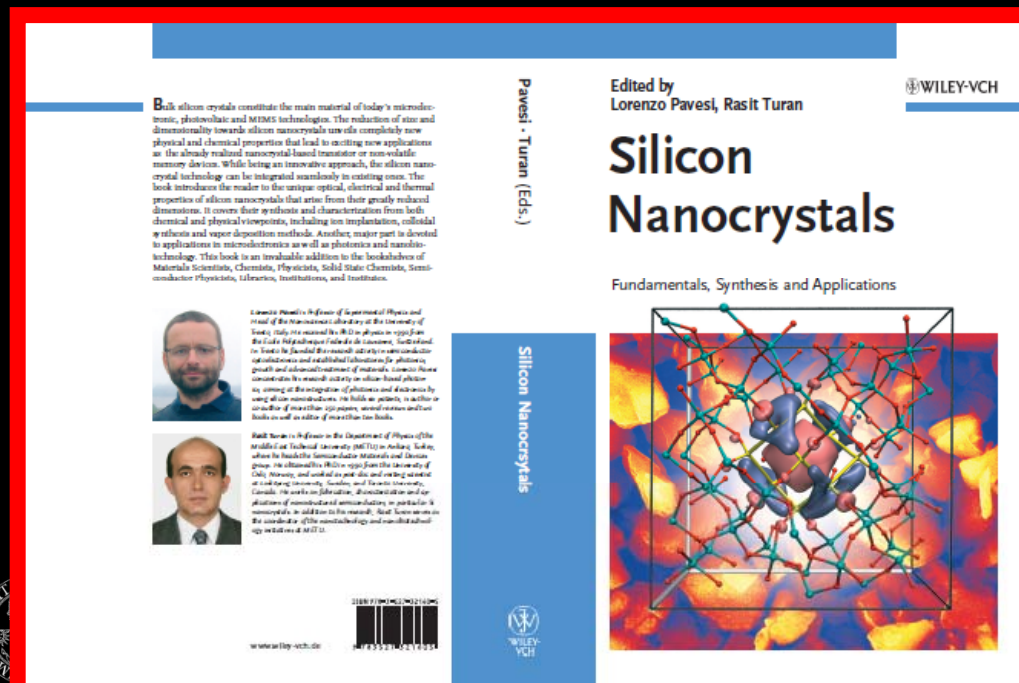


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Nanosilicon photonics: a platform where silicon nanoclusters enable new functionalities in silicon photonics



508
Laser & Photonics Reviews
Laser & Photon. Rev. 3, No. 6, 508–534 (2009) / DOI 10.1002/lpor.200810045

Abstract. Silicon photonics is no longer an emerging field of research and technology but a present reality with commercial products available on the market, where low-dimensional silicon (nanosilicon or nano-Si) can play a fundamental role. After a brief history of the field, the optical properties of silicon reduced to nanometric dimensions are introduced. The use of nano-Si, in the form of Si nanocrystals, in the main building blocks of silicon photonics (waveguides, modulators, sources and detectors) is reviewed and discussed. Recent advances of nano-Si devices such as waveguides, optical resonators (linear, rings, and disks) are treated. Emphasis is placed on the visible optical gain properties of nano-Si and to the sensitization effect on Er ions to achieve infrared light amplification. The possibility of electrical injection in light-emitting diodes is presented as well as the recent attempts to exploit nano-Si for solar cells. In addition, nonlinear optical effects that will enable fast all-optical switches are described.

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Nanosilicon photonics

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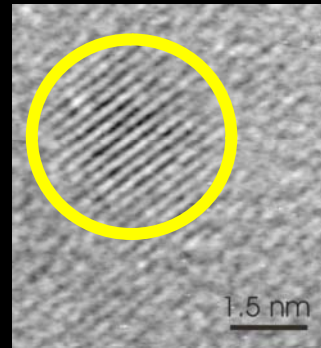
Received: 25 August 2008, Revised: 6 February 2009, Accepted: 11 March 2009
Published online: 2 June 2009

Key words: Nanosilicon, photonics, optical amplification, non-linear properties.

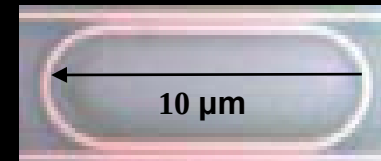
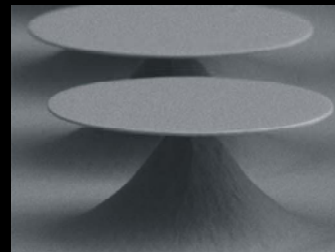
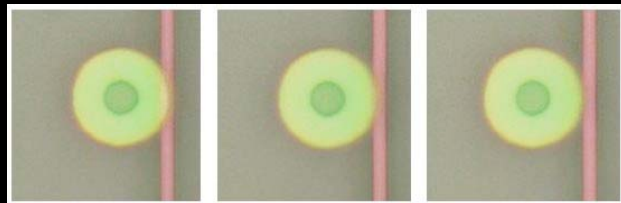
PACS: 42.62.-b, 42.65.-k, 78.67.Bf, 81.07.-b, 85.60.-q

Silicon Nanophotonics

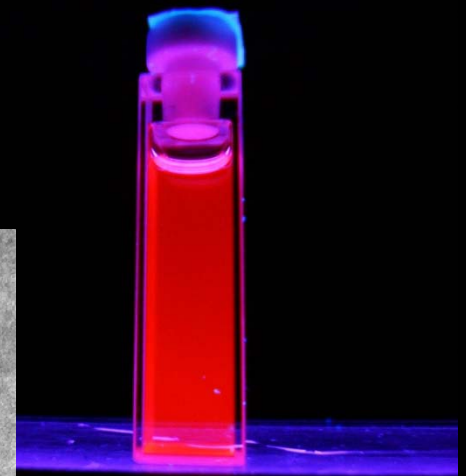
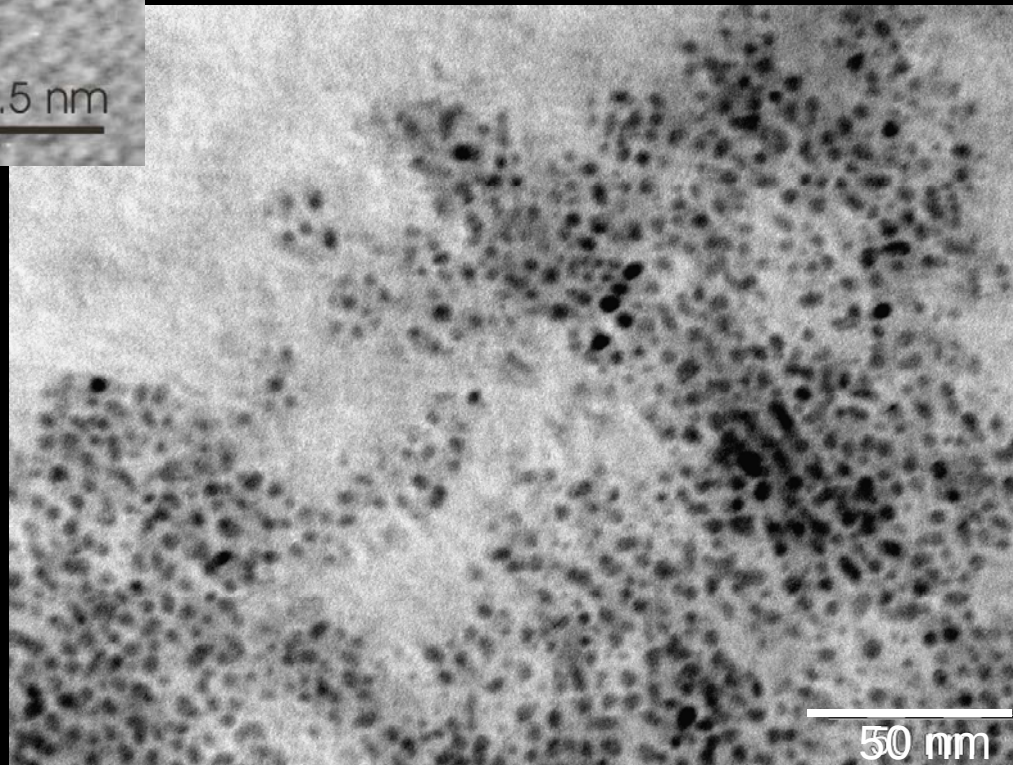
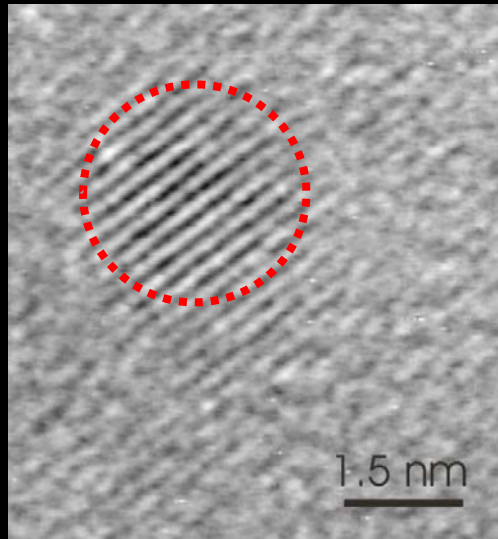
- Confine carriers on nanoscale dimensions



- Confine photons on nanoscale dimensions



Silicon quantum dots



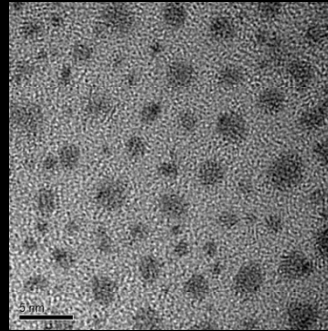
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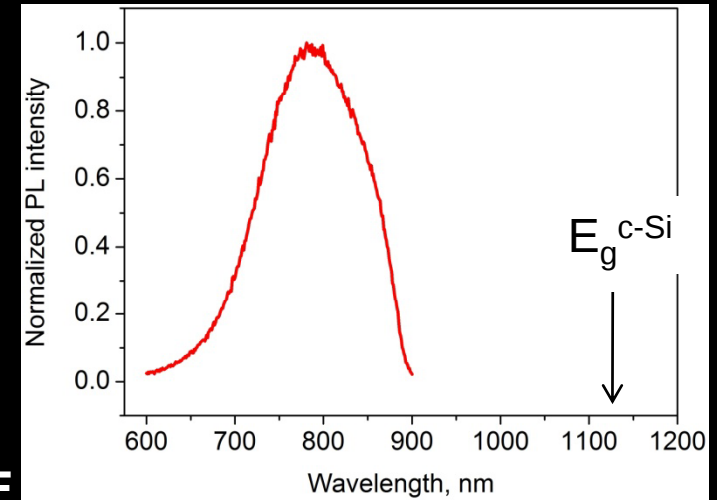
Silicon quantum dots



Bulk Silicon:
Indirect band-gap
inefficient light emitter



Nanocrystalline-Si:
Direct-gap due to QCE
Strong visible light emission



Optical gain in silicon nanocrystals

L. Pavesi[†], L. Dal Negro[†], C. Mazzoleni[†], G. Franzò[†] & F. Priolo[†]

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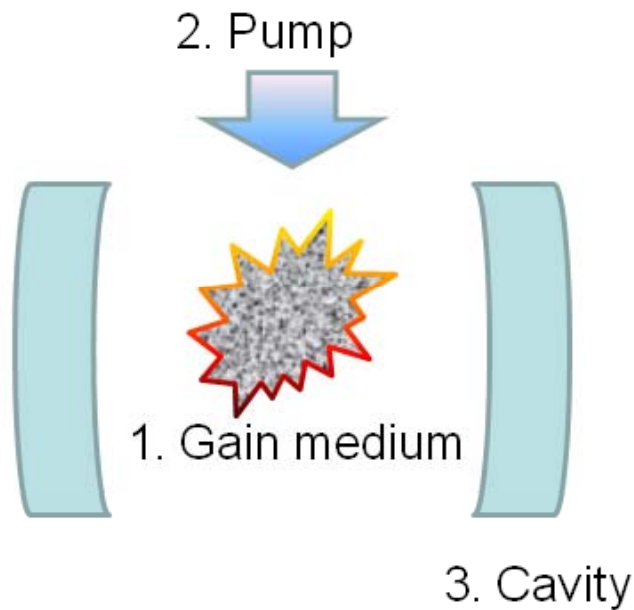
Optical gain in silicon nanocrystals

L. Pavesi*, L. Dal Negro*, C. Mazzoleni*, G. Franzò† & F. Priolo†

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Silicon laser ?

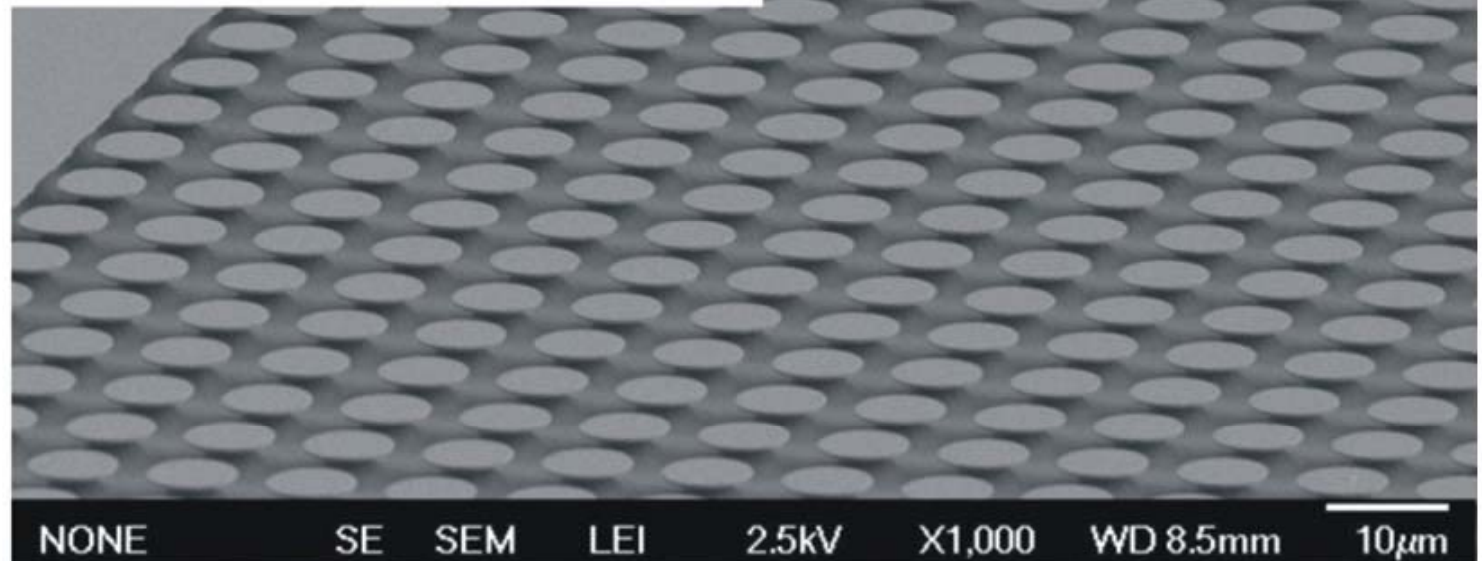
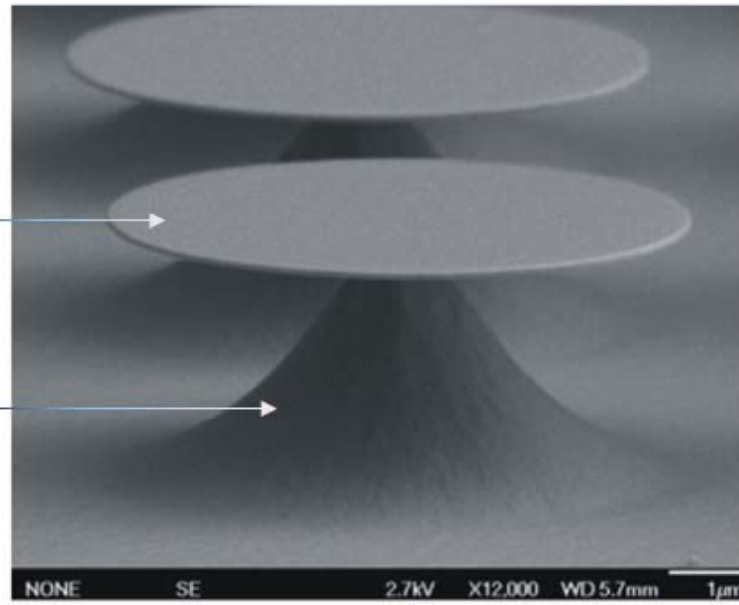


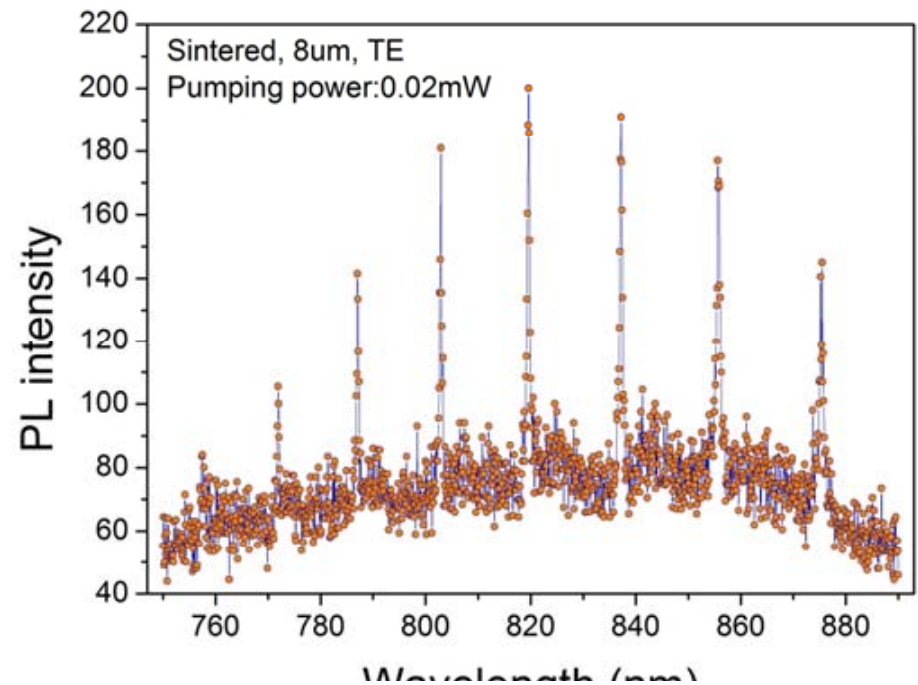
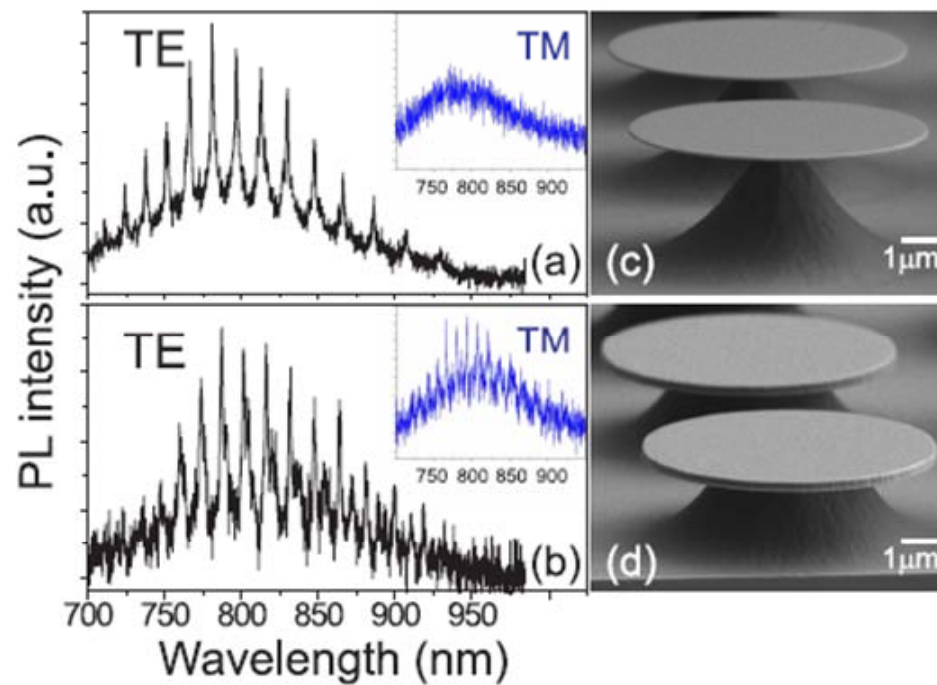
e.g., a **Whispering-gallery mode resonator**

Si QD's in 2D whispering-gallery resonators

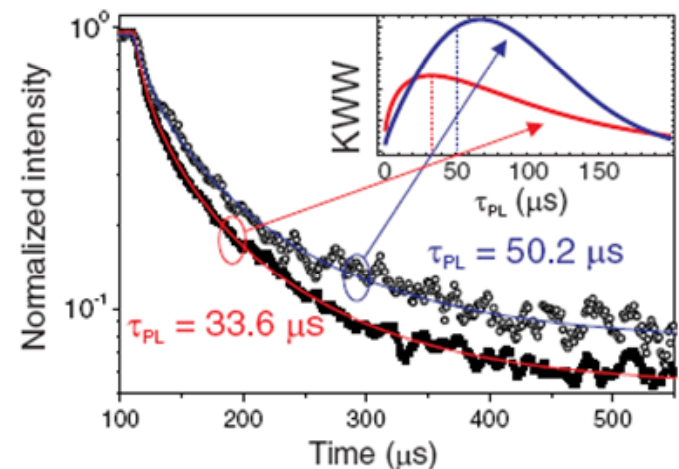
Si-nc/SiO₂

c-Si



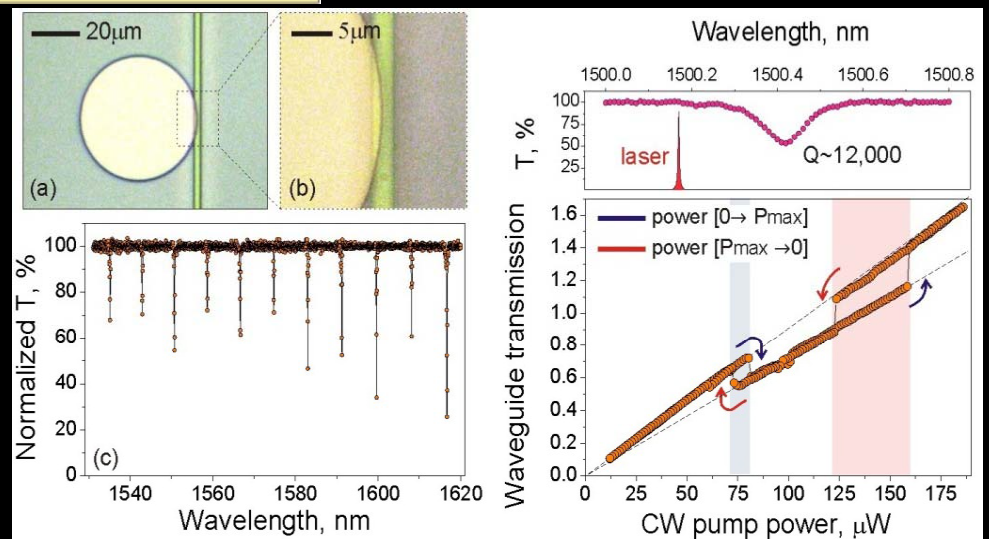
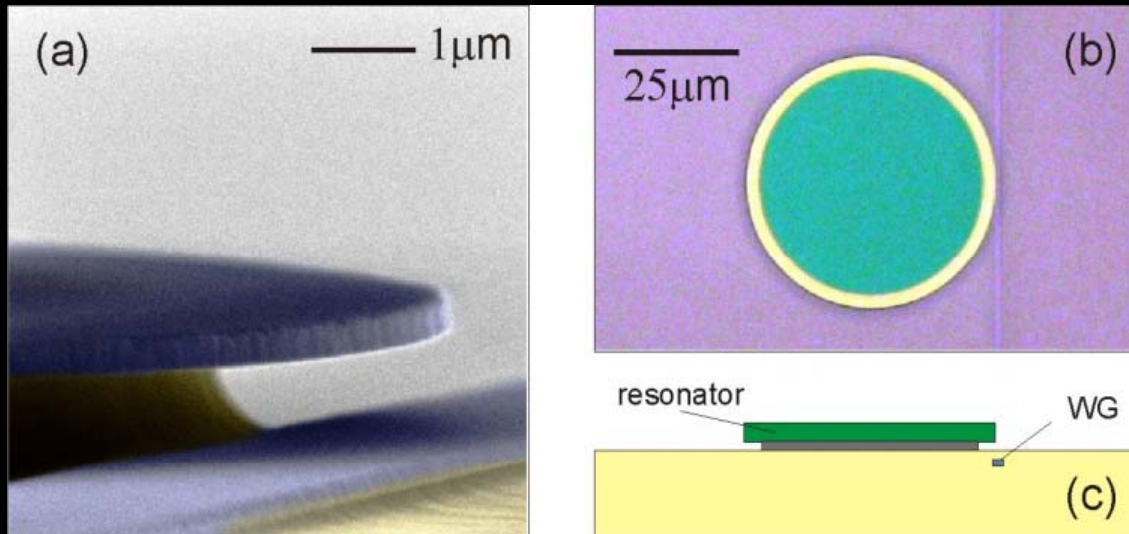


Purcel effect



M. Ghulinyan, D. Navarro-Urrios, A. Pitanti, Alberto Lui, Georg Pucker, L. Paves
 OPT. EXPRESS **16**, 13218-13224 (2008)

Integration of microdisk with a waveguide

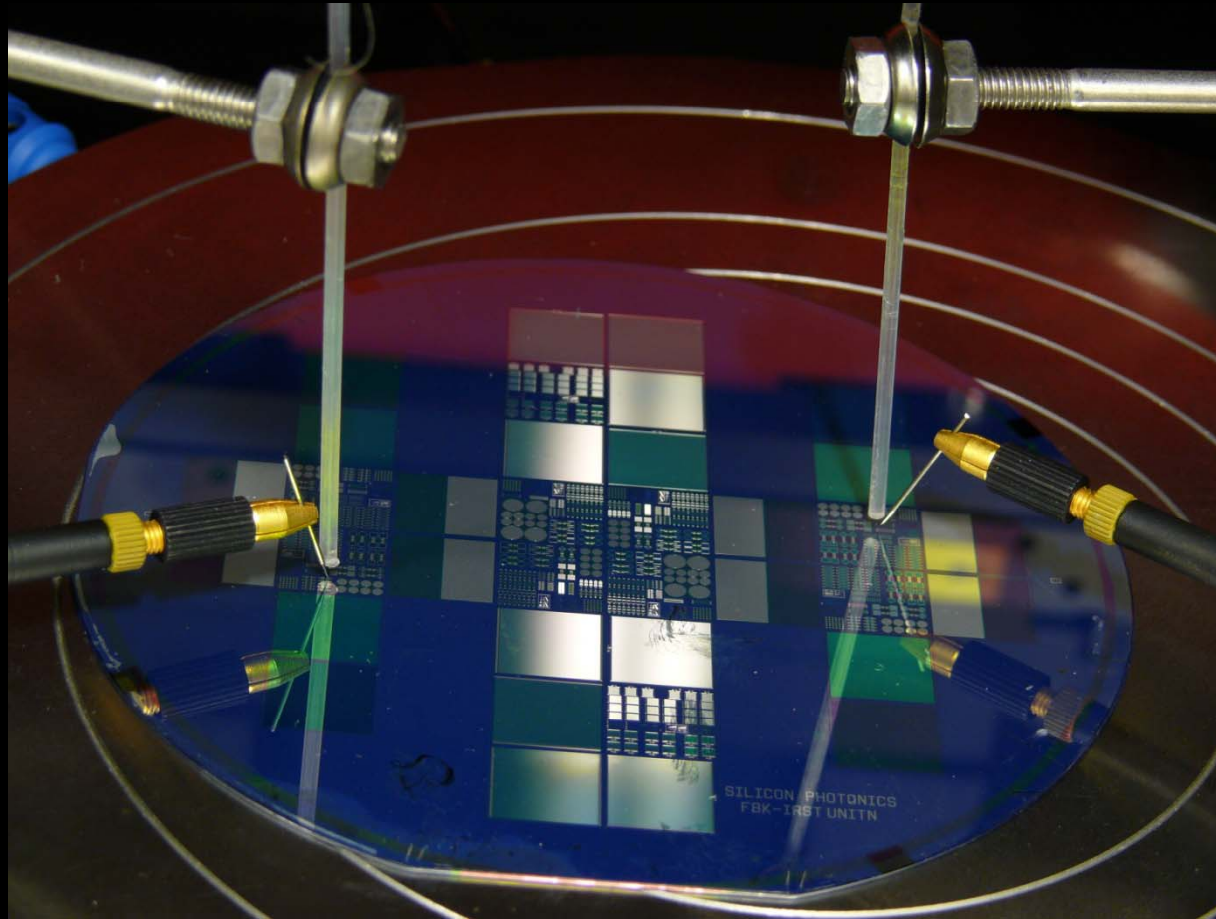


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pHotonics ELelectronics functional Integration on CMOS

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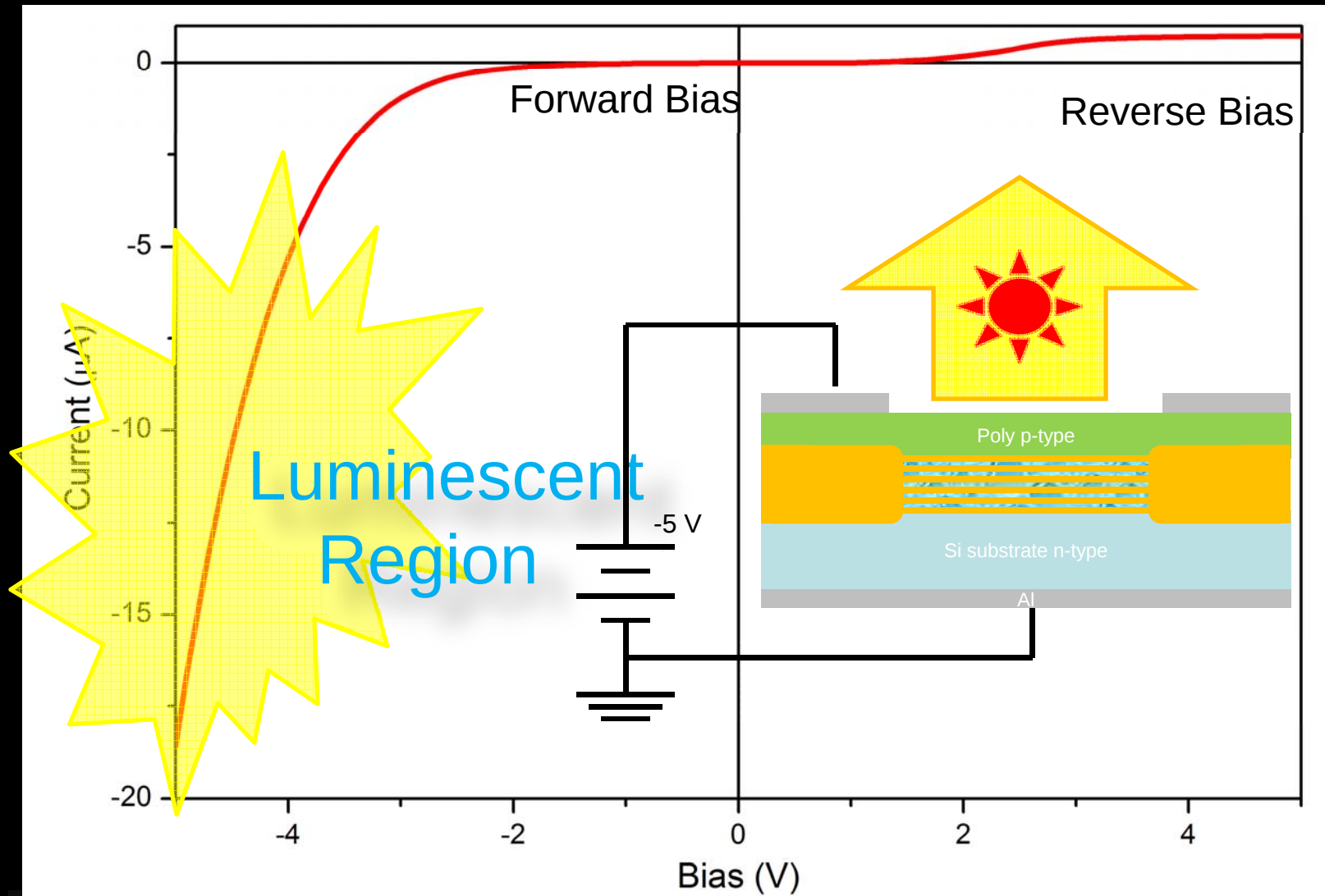


Marconi, Anopchenko

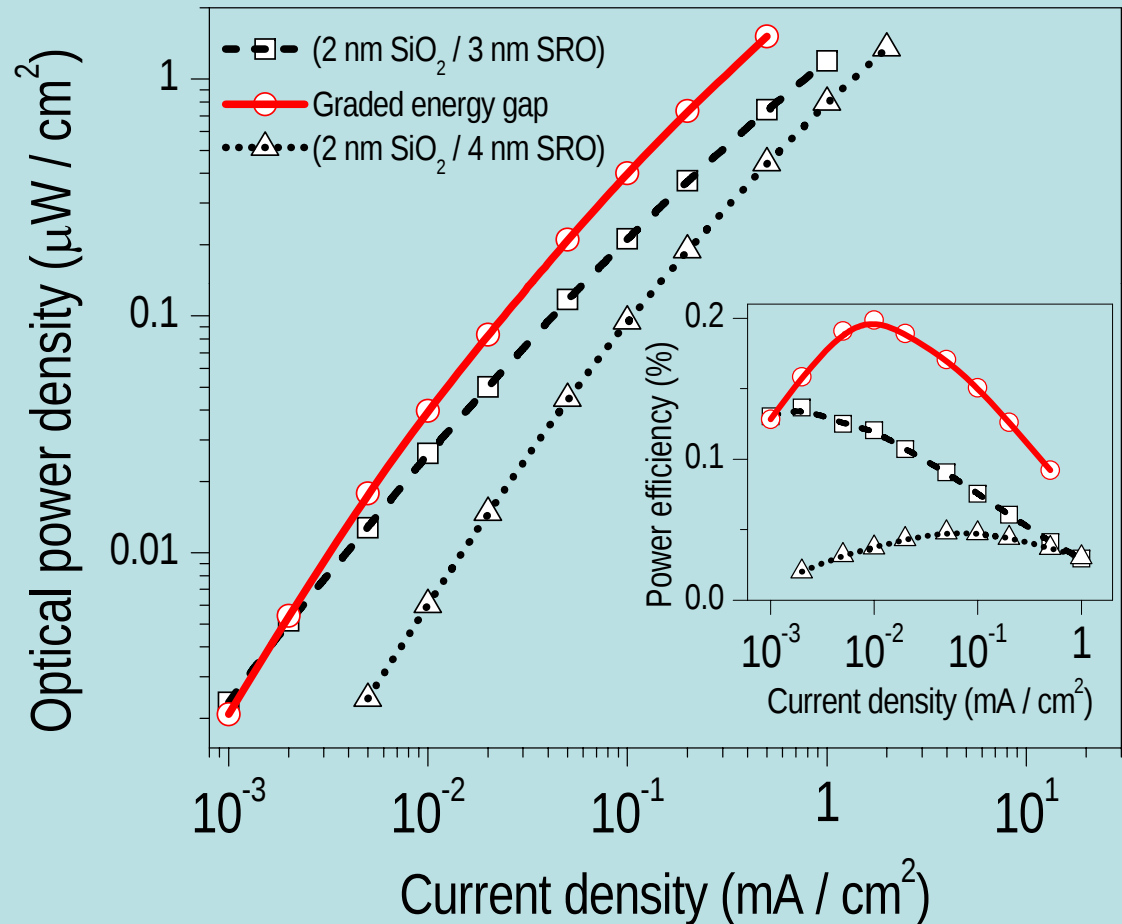
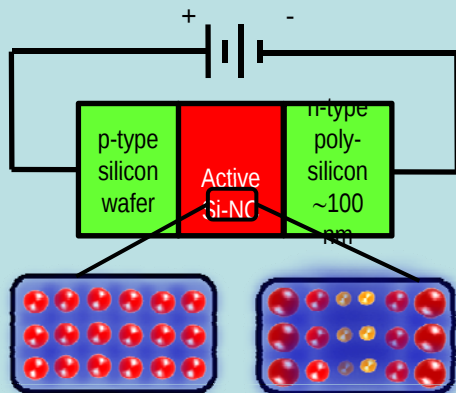
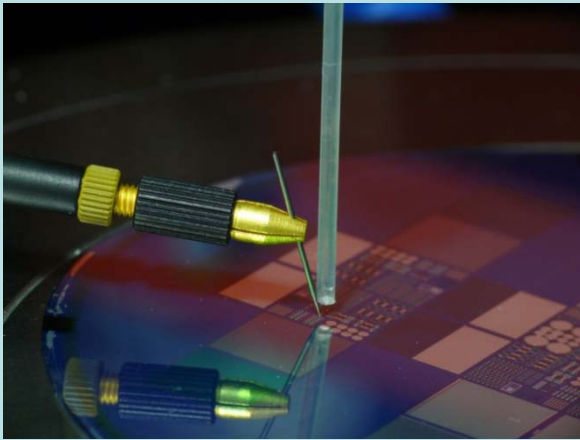


*pHotonics E*lectronics functional Integration on CMOS

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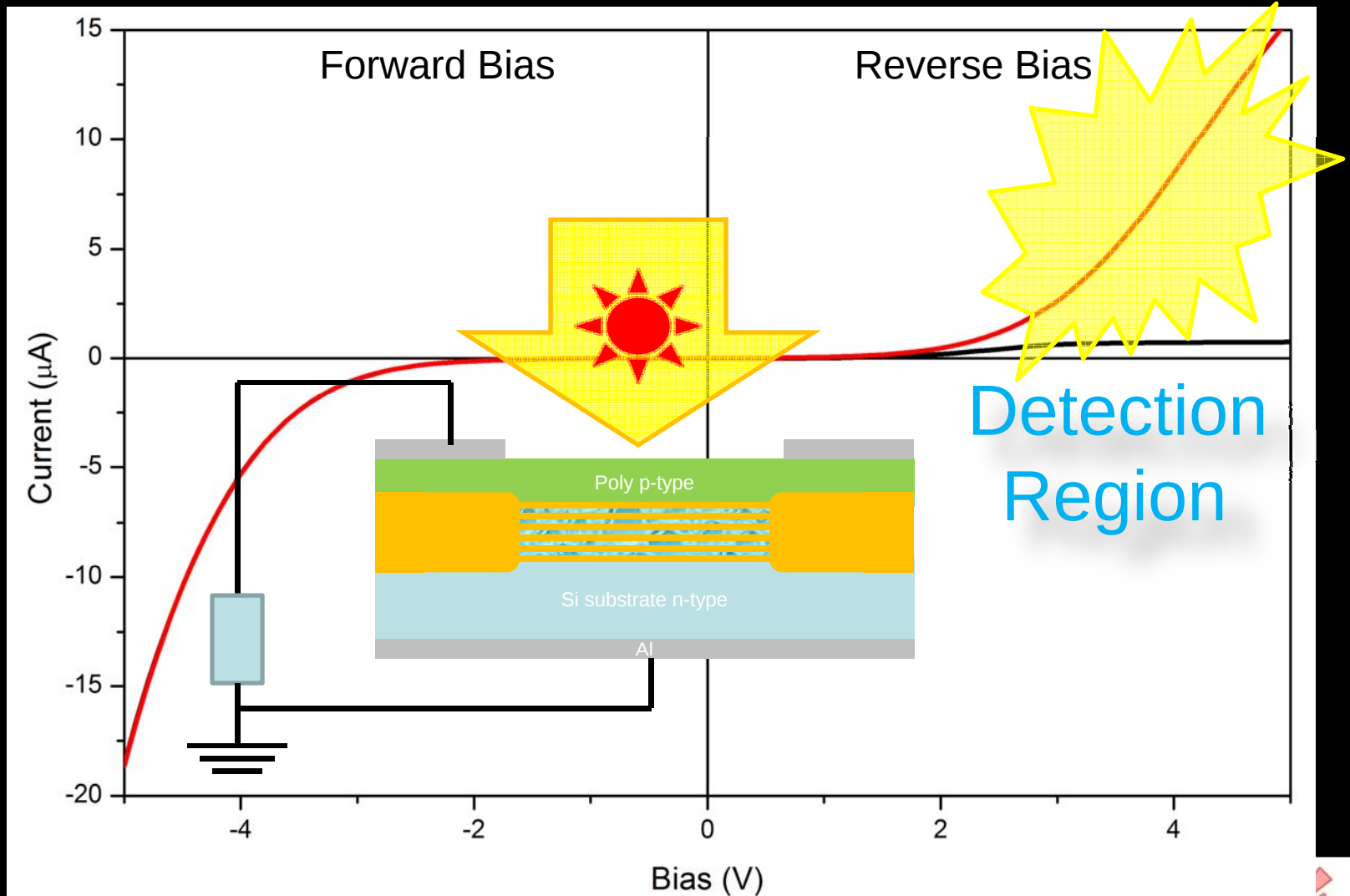


pHotonics ELelectronics functional Integration on CMOS



*pHotonics E*lectronics functional Integration on CMOS

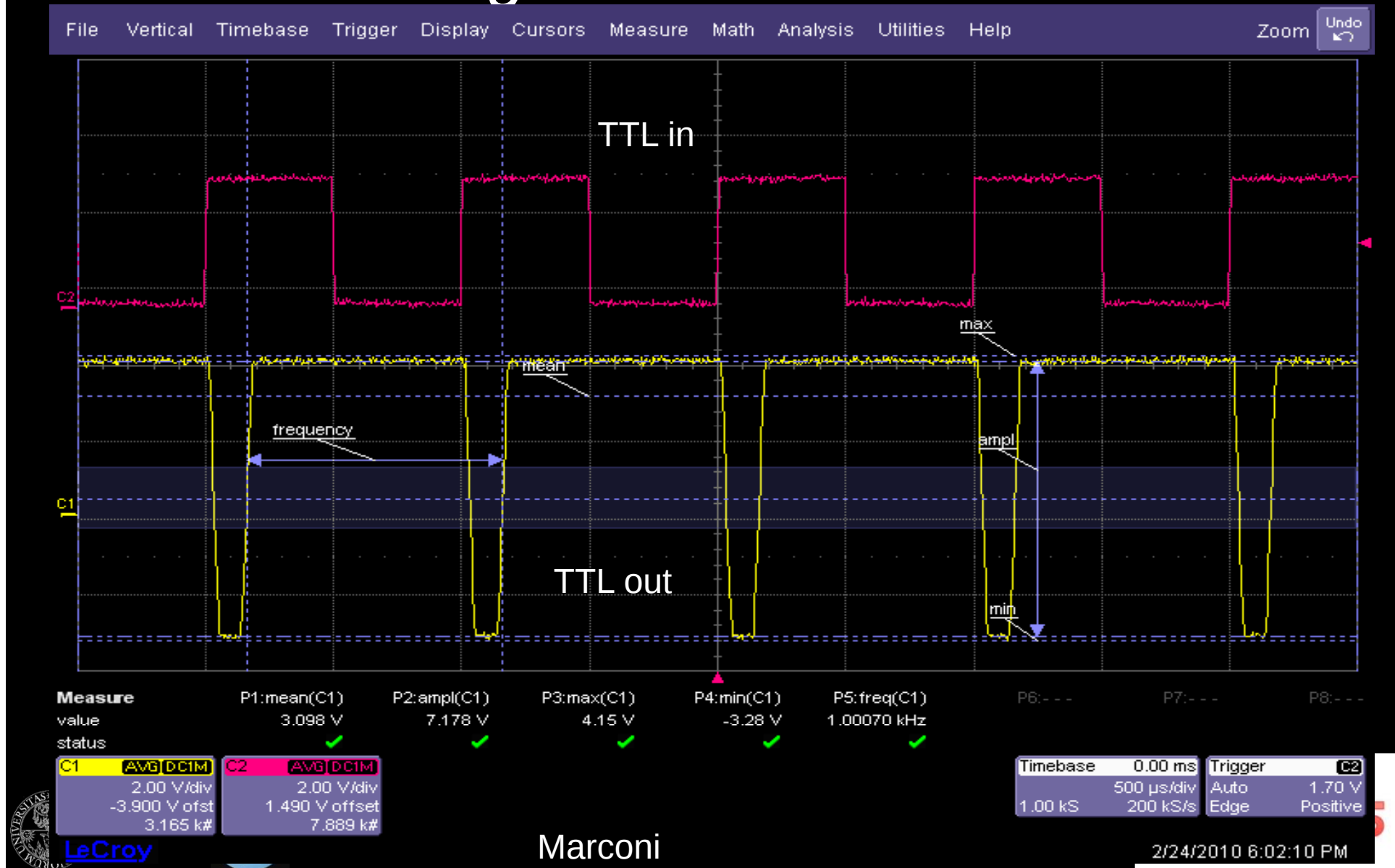
THE all SILICON TRANSCIEVER



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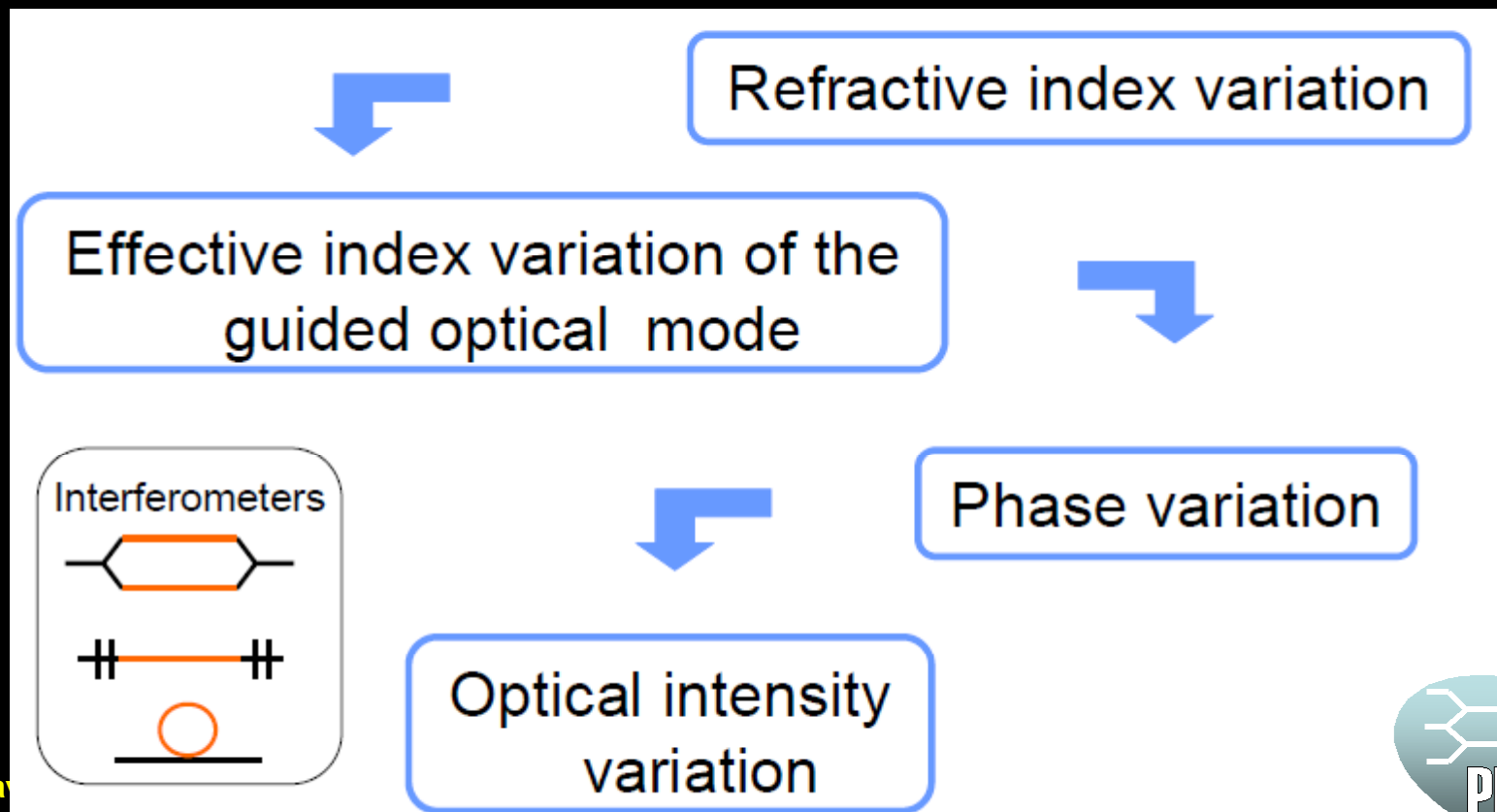
*pHotonics E*lectronics functional Integration on CMOS



All optical switching with silicon nanocrystals

$$n=n_0+n_2 I$$

$$\alpha=\alpha_0+\beta I$$



Comparison to other nonlinear materials

Silica



$$n_2 = (1.54 \times 10^{-16}) \text{ cm}^2/\text{W} [3,4]$$

Bulk Silicon



$$n_2 = (4.5 \times 10^{-14}) \text{ cm}^2/\text{W} [3,4]$$

GaAs



$$n_2 = (1.59 \times 10^{-13}) \text{ cm}^2/\text{W} [5]$$

Si-ncs



$$n_2 = (2 \div 8 \times 10^{-13}) \text{ cm}^2/\text{W} [\text{present work}]$$

[3] Handbook of Nonlinear Optics

[4] Adair R. et al., Physical Review B, 39, 3337, (February 1989).

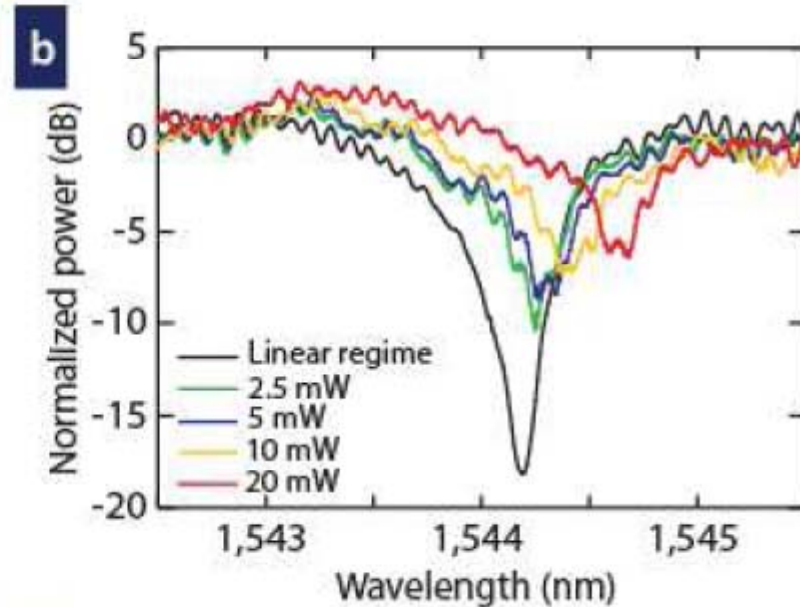
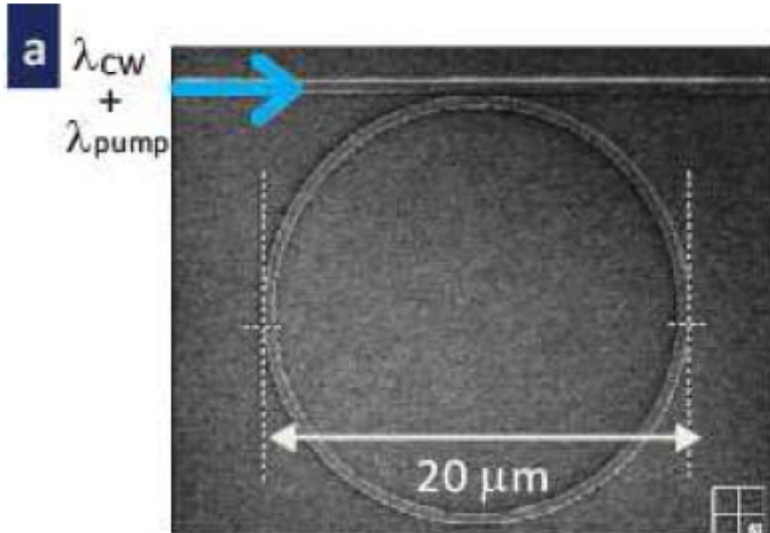
[5] M. Dinu et al., Applied Physics Letters, 82, 2954 (2003).



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All optical switching



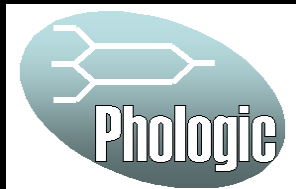
Si nanocrystals activated slot waveguides

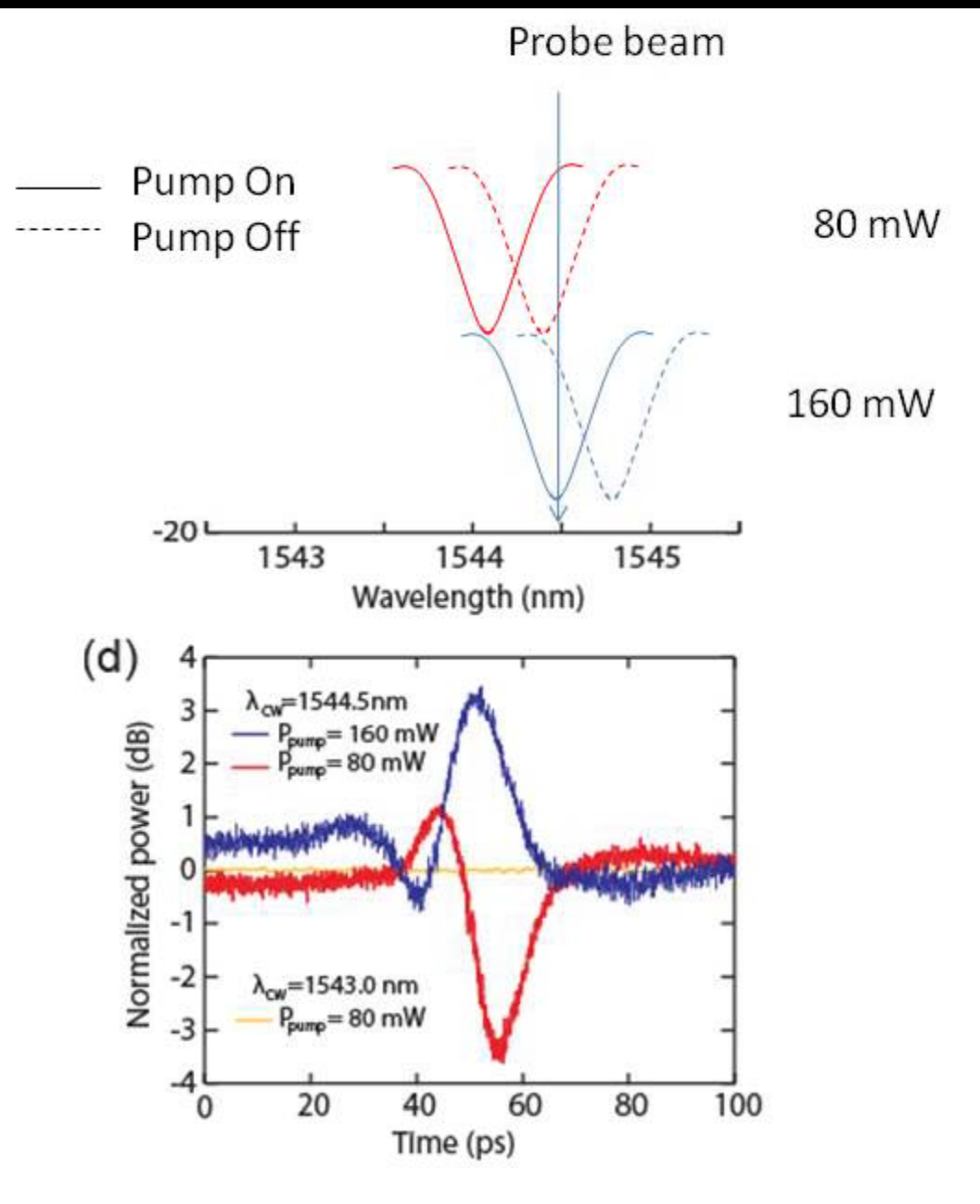


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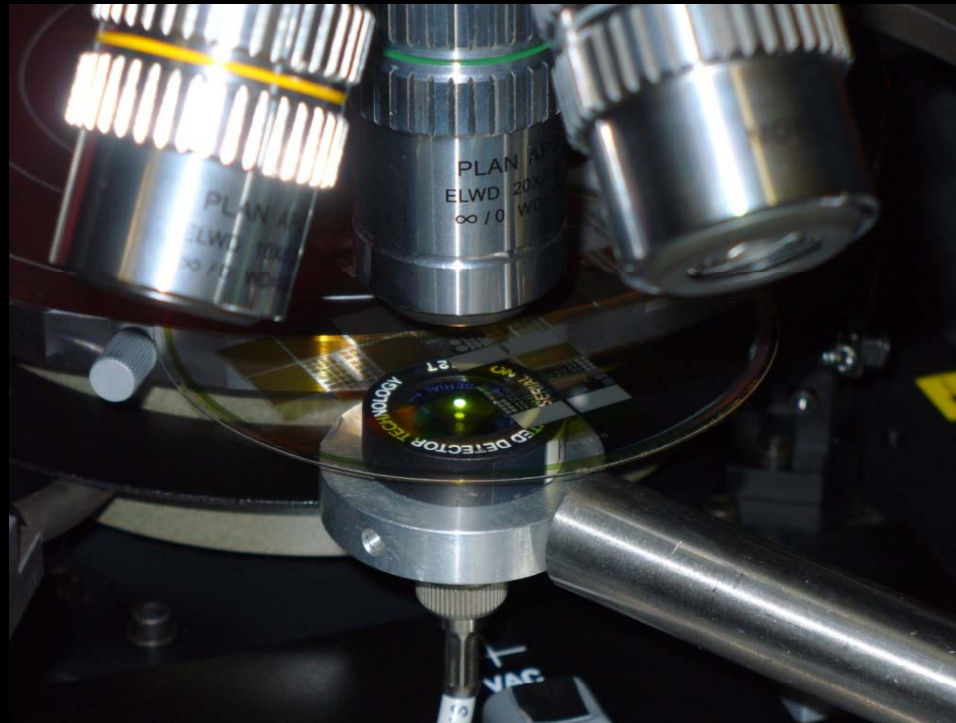


A. Martinez et al. Nanoletters (2010)





Improved photovoltaic efficiency by applying novel effects at the limits of light-matter interaction



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Improved photovoltaic efficiency by applying novel effects at the limits of light-matter interaction

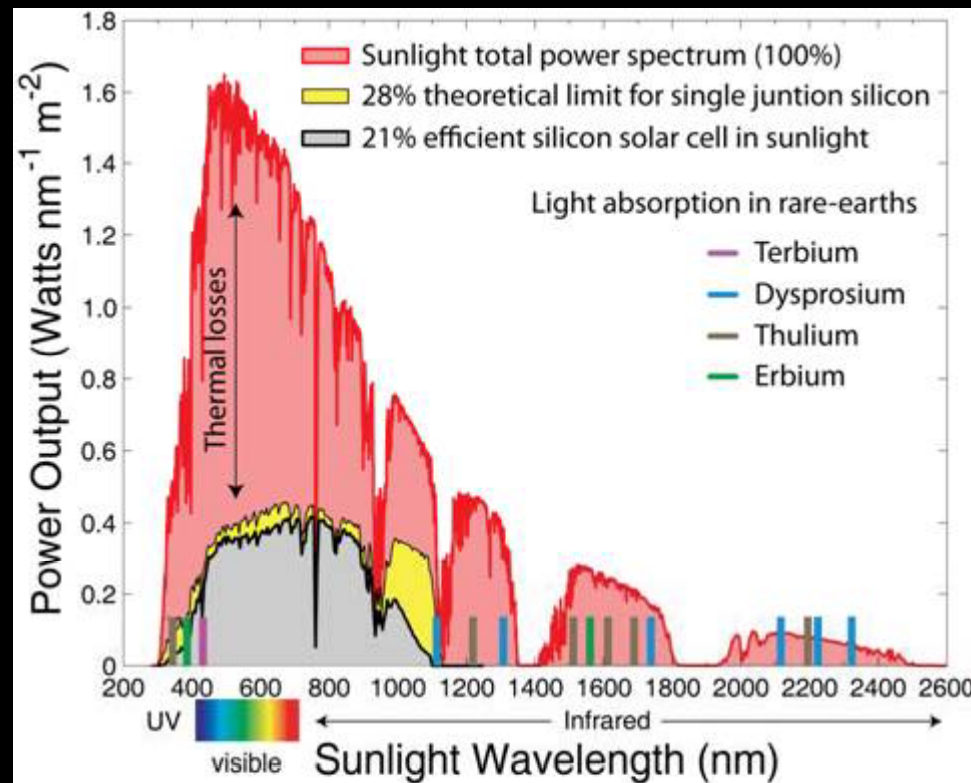
Photon electron energy conversion	32.9%
Unabsorbed energy loss	18.7%
Heat loss	46.8%
Other losses	1.6%



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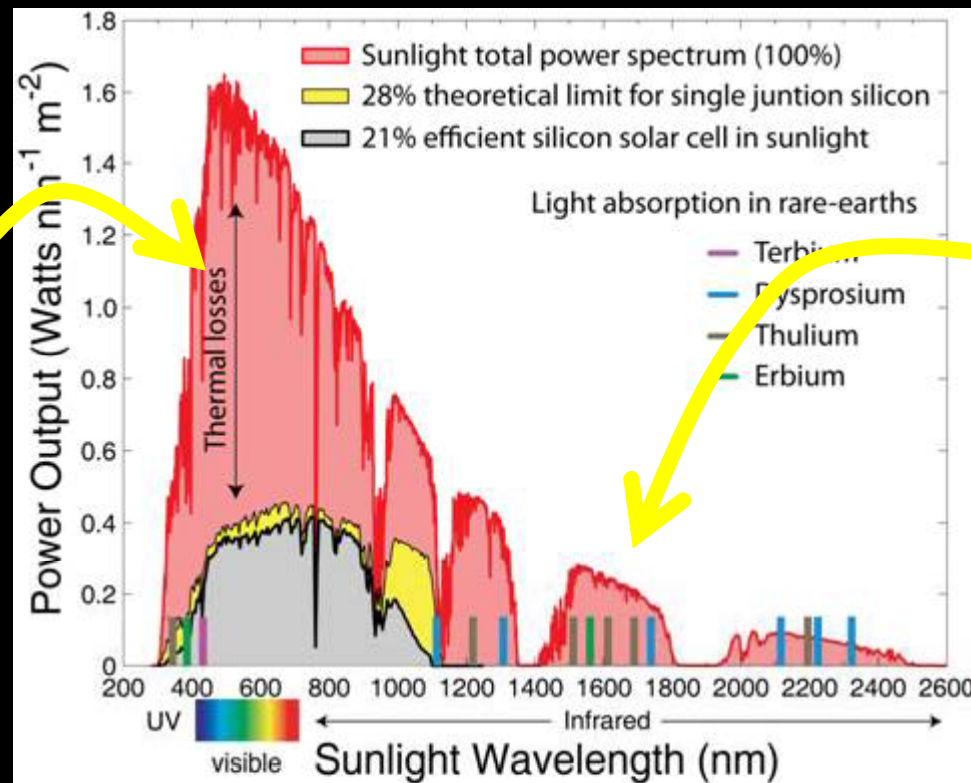


Improved photovoltaic efficiency by applying novel effects at the limits of light-matter interaction



Improved photovoltaic efficiency by applying novel effects at the limits of light-matter interaction

downshifter



Secondary carrier generation



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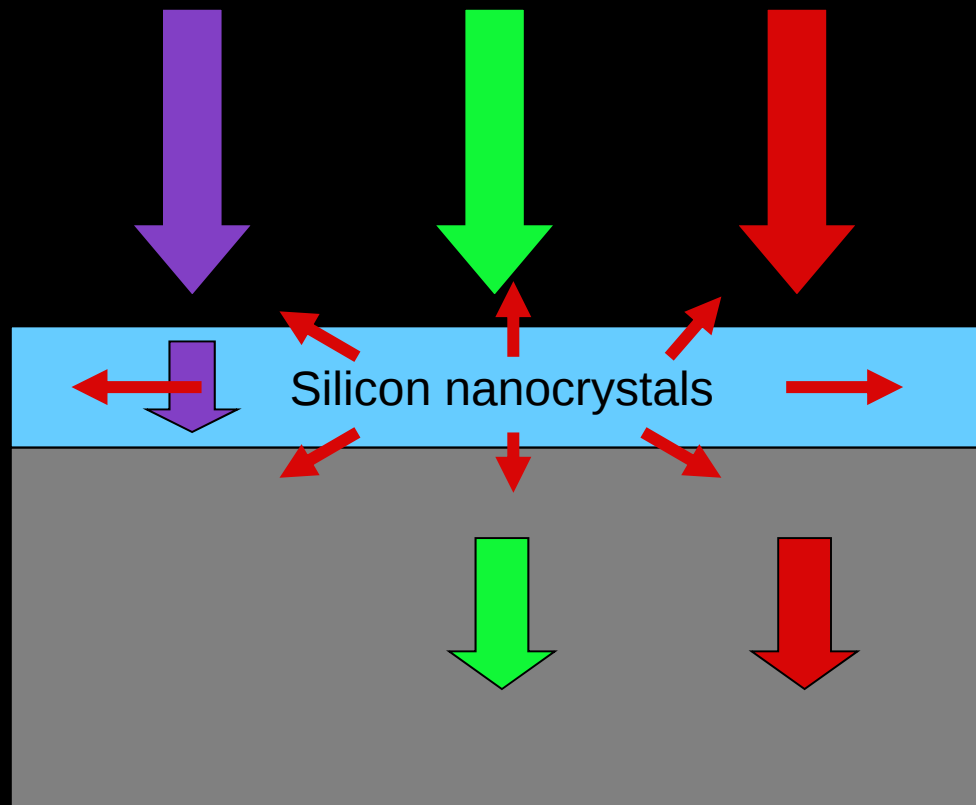


Ryan, Anopchenko, Marconi – APP FBK



Improved photovoltaic efficiency by applying novel effects at the limits of light-matter interaction

downshifter



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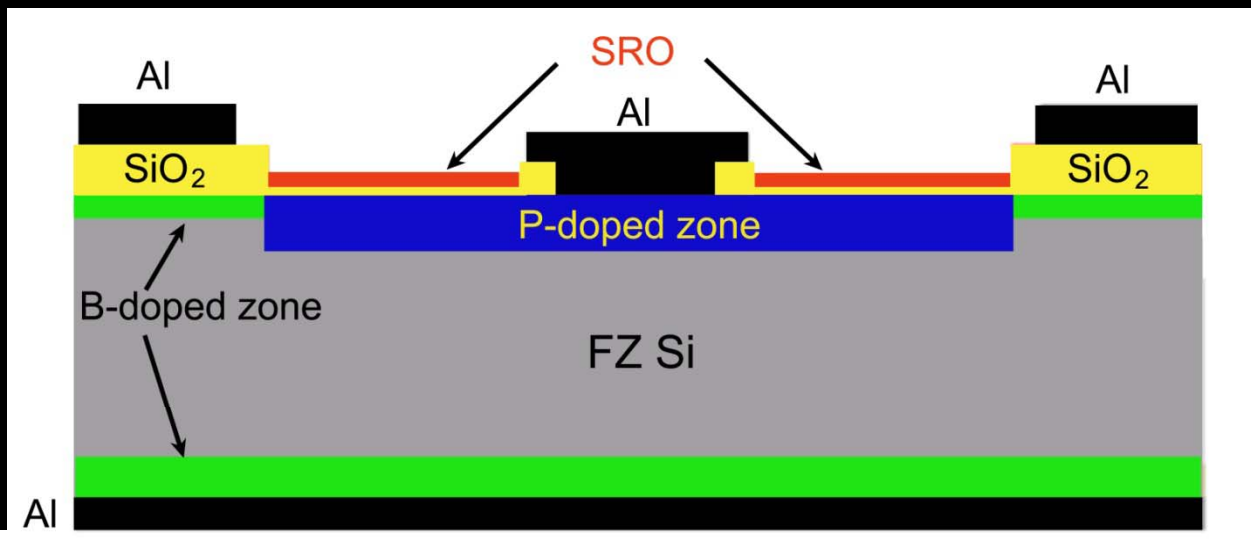


Ryan, Anopchenko, Marconi – APP FBK



Improved photovoltaic efficiency by applying novel effects at the limits of light-matter interaction

downshifter

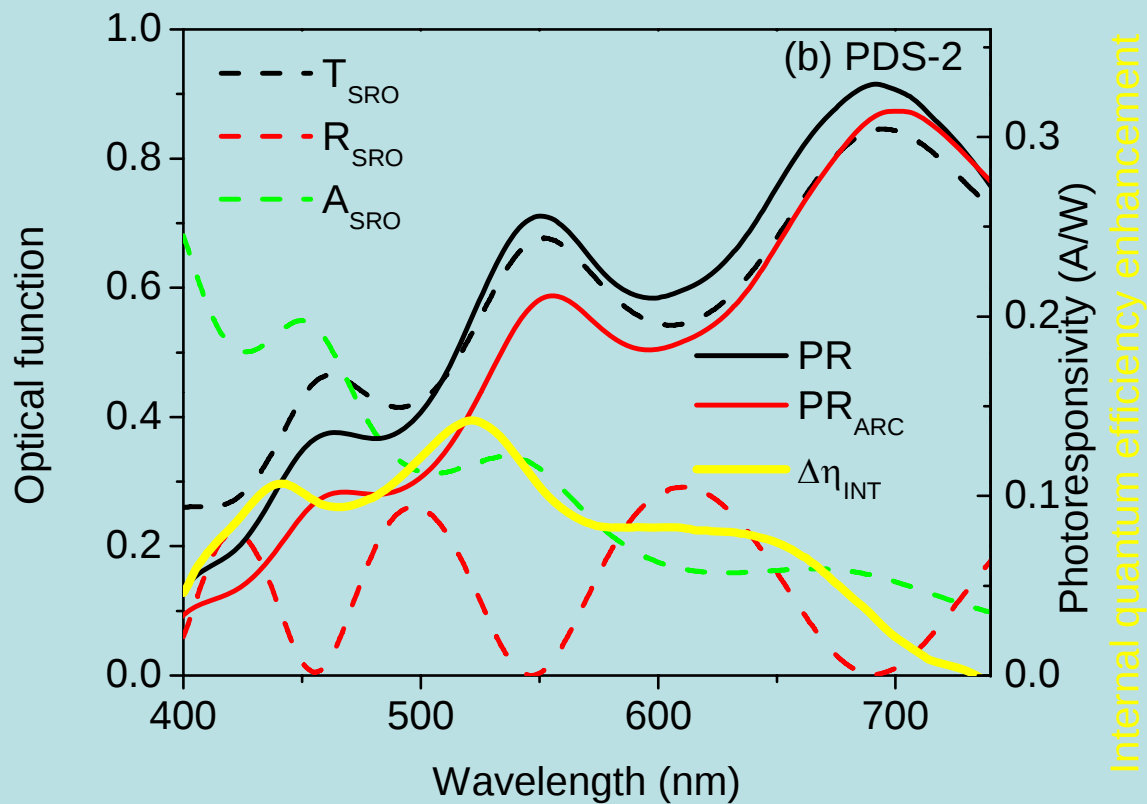


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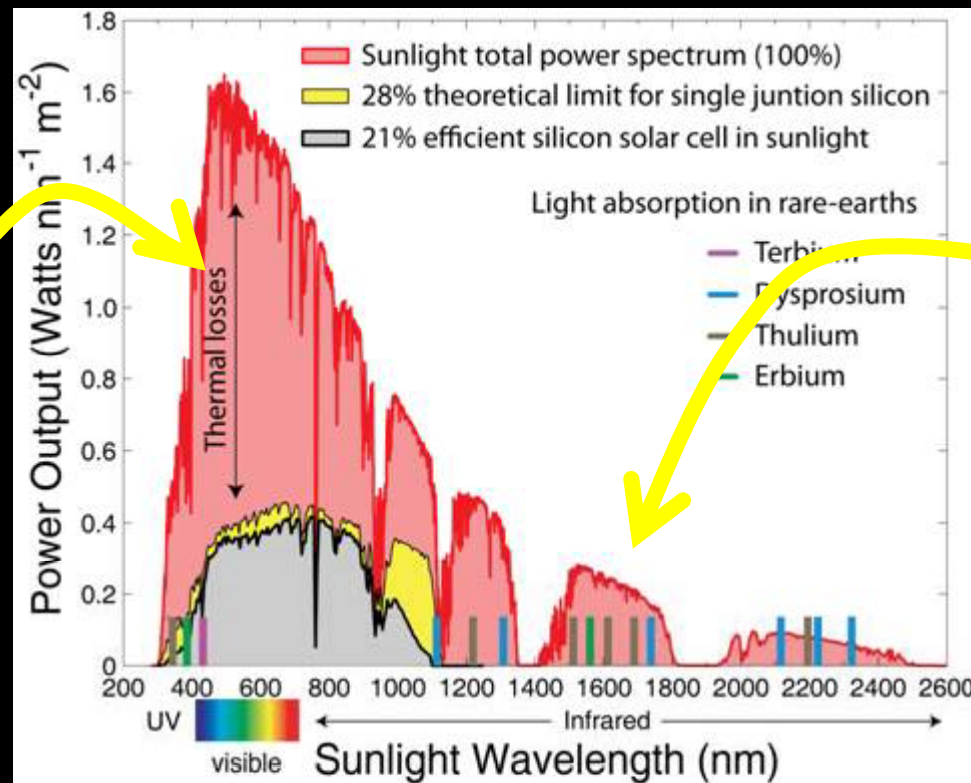


A maximum enhancement of the internal quantum efficiency of 14%



Improve photovoltaic efficiency by applying novel effects at the limits of light-matter interaction

downshifter



Secondary carrier generation



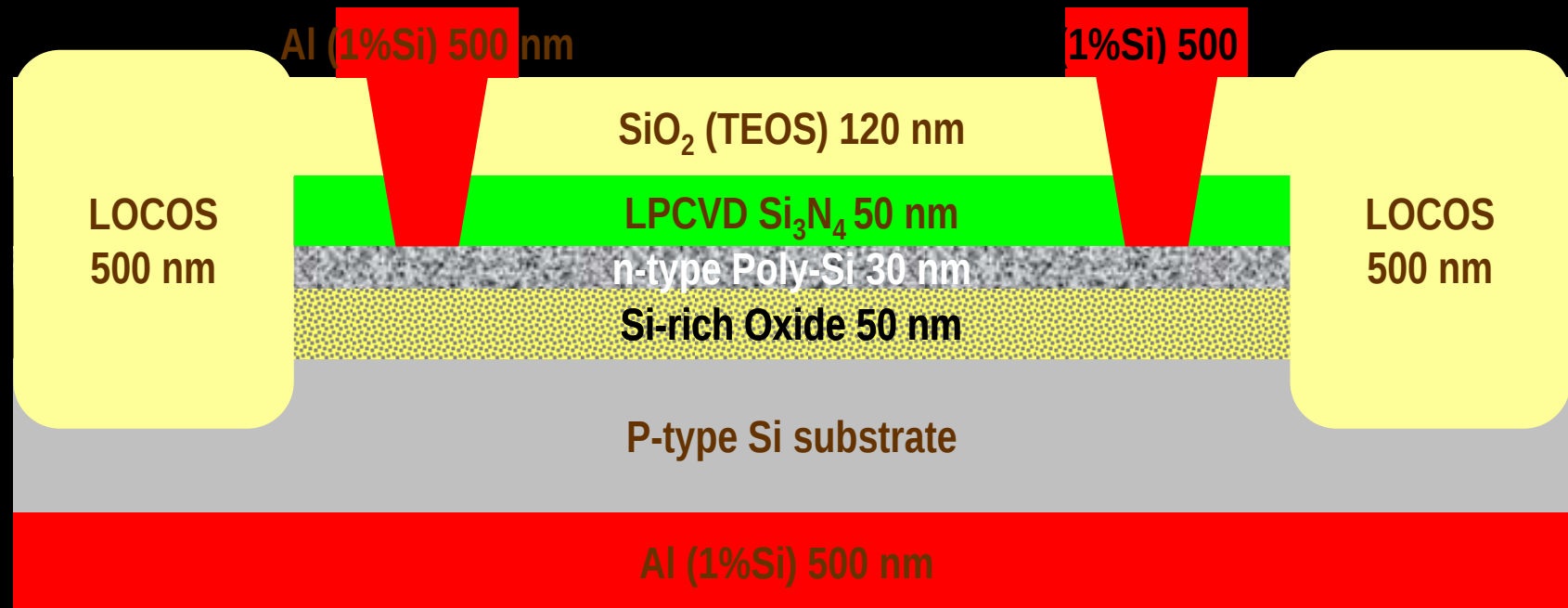
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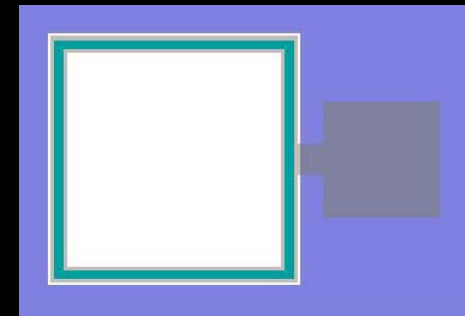
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Cross section of the device



Device area = 320 μm X 320 μm



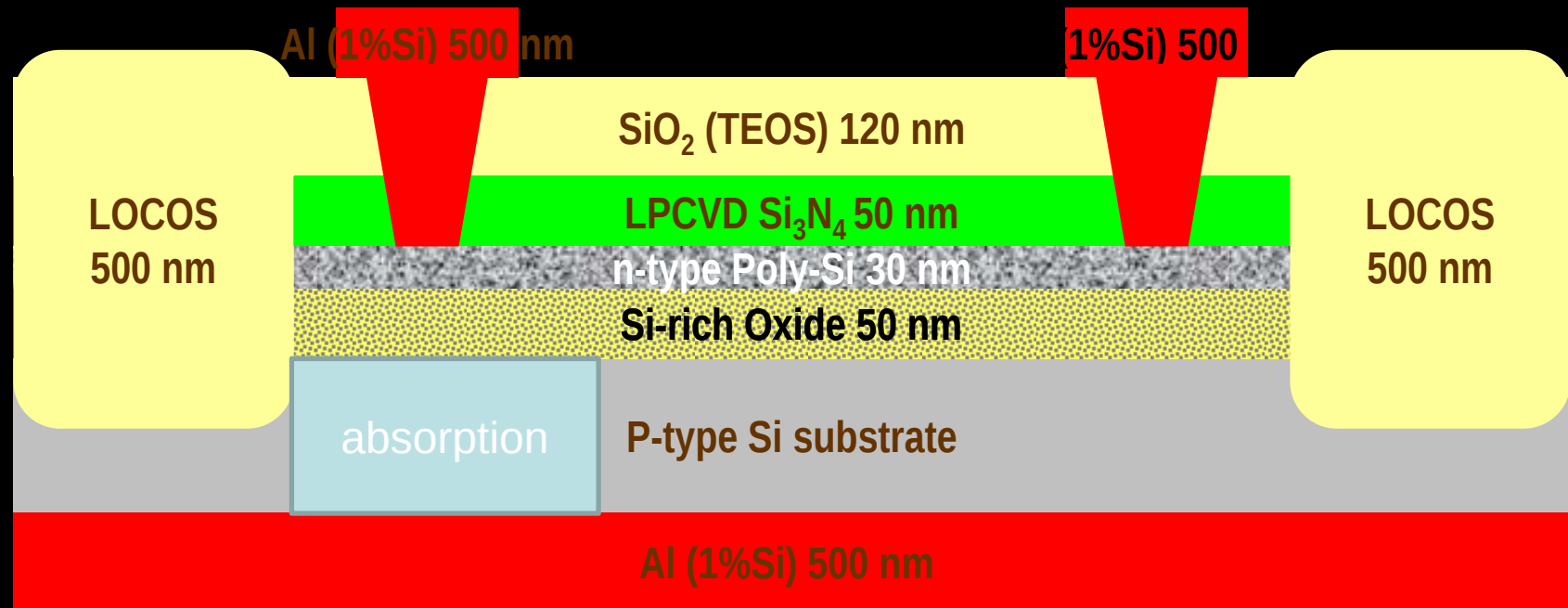
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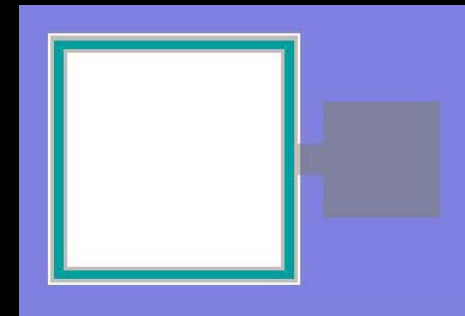
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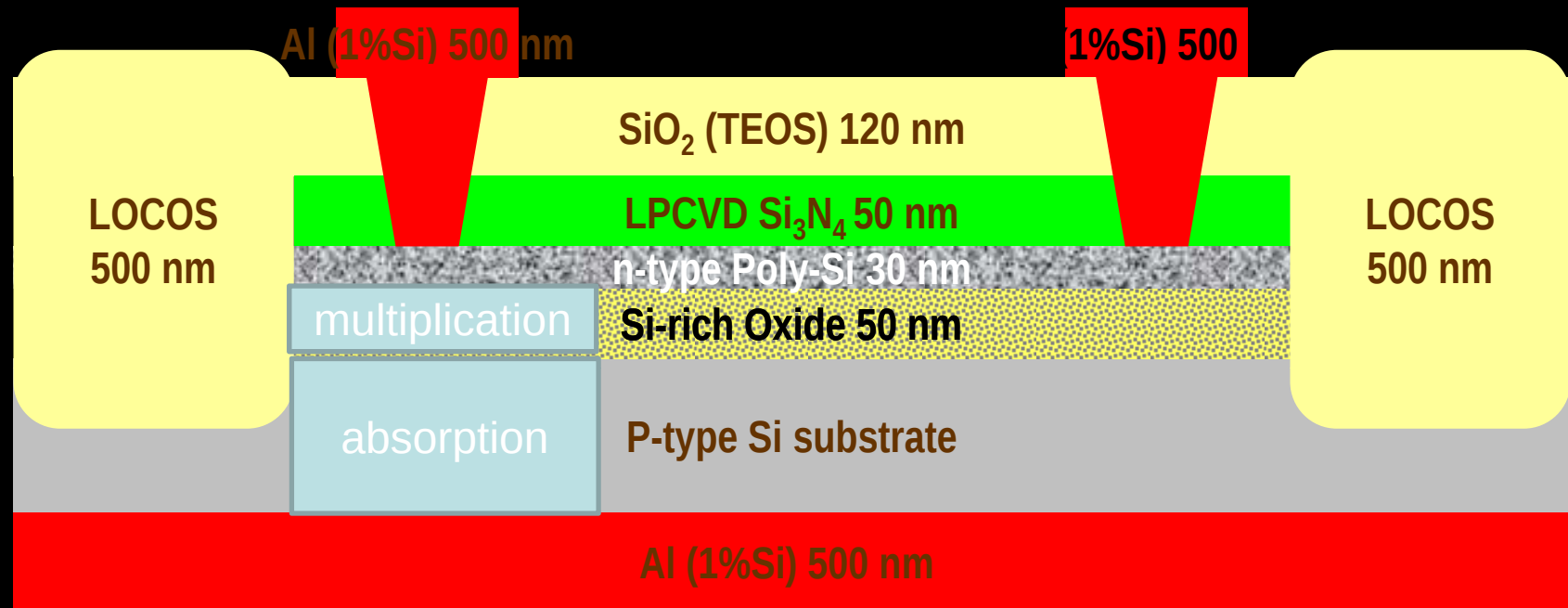
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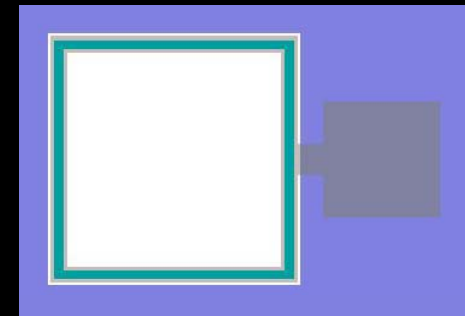
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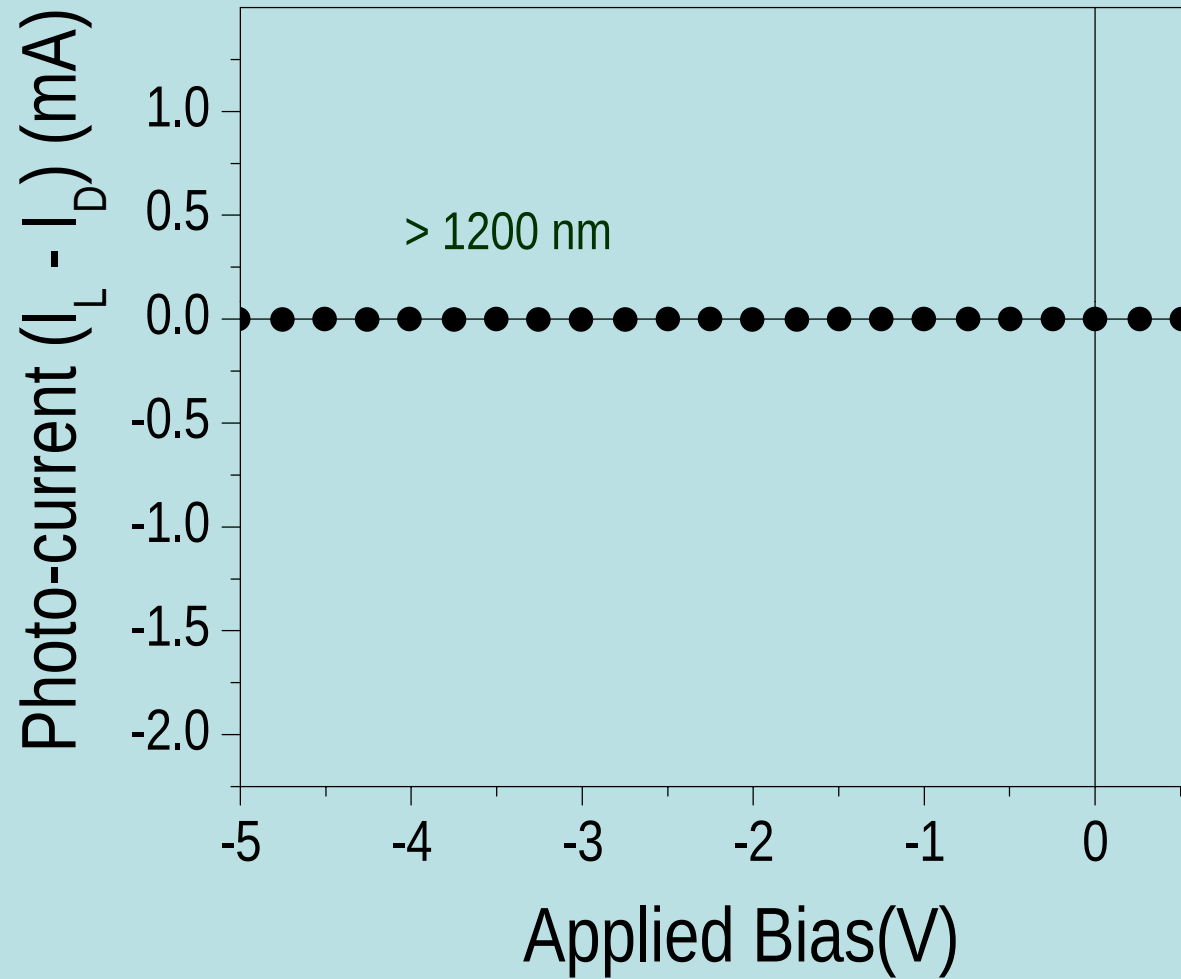
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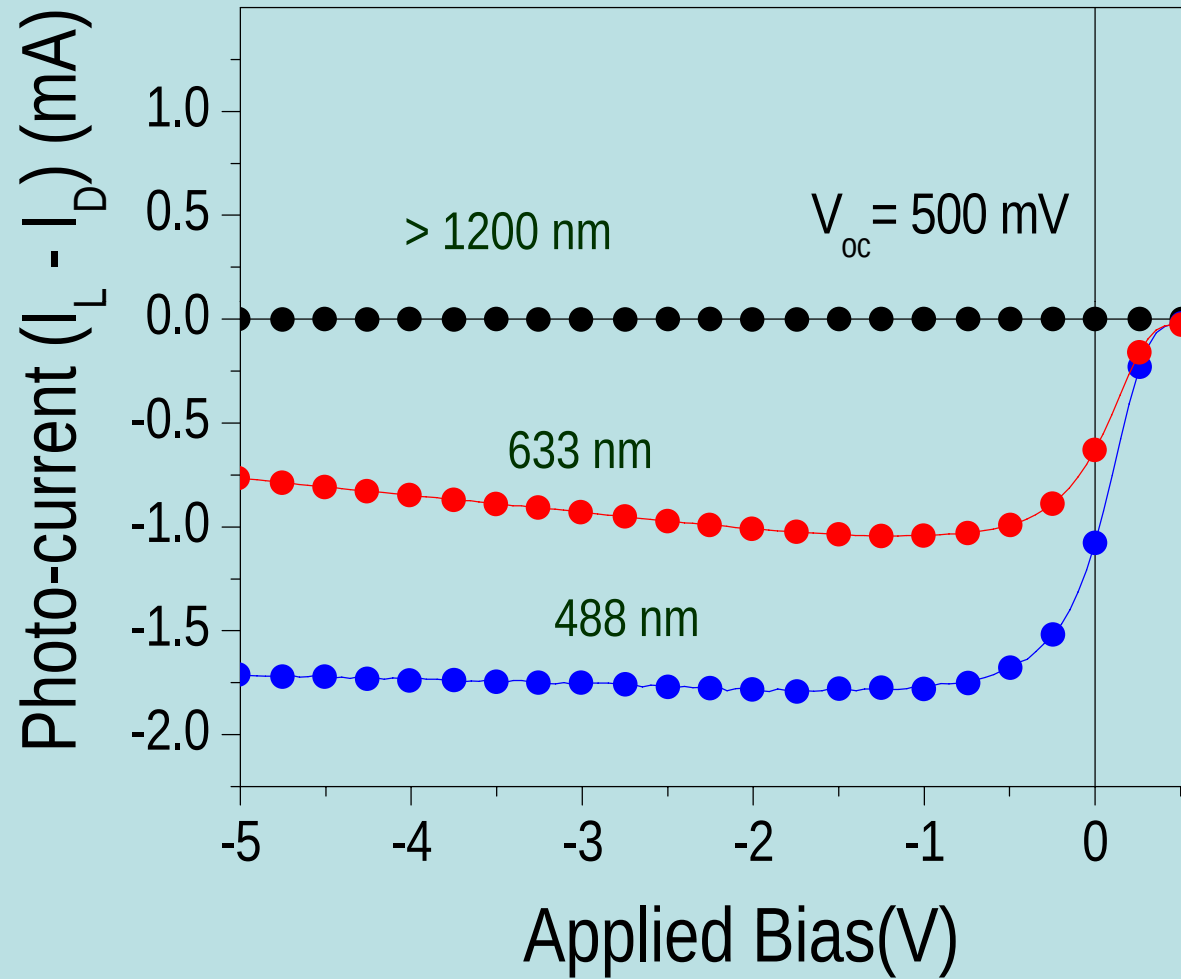
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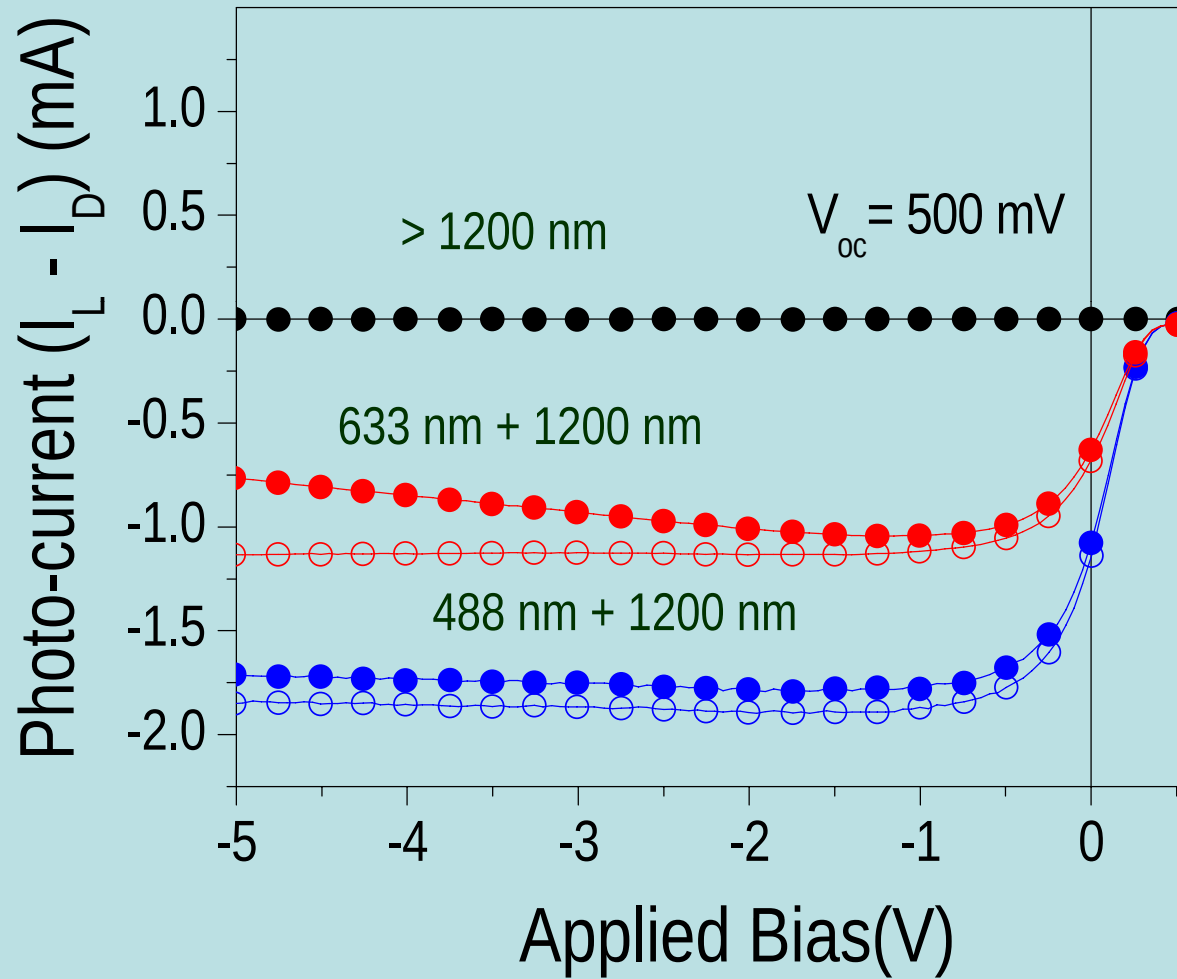
IR response in $\Gamma 3N$



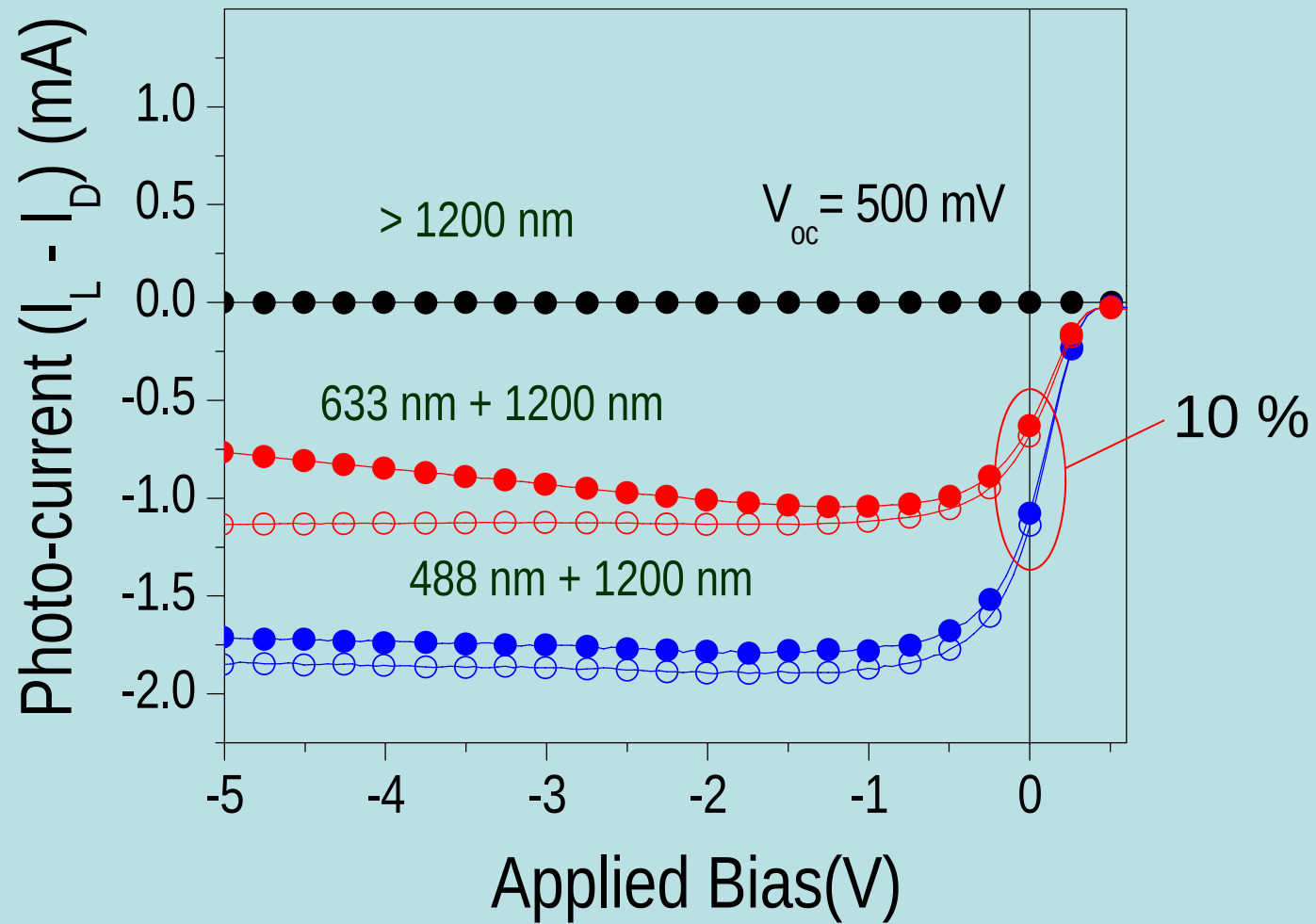
IR response in $\Gamma 3N$



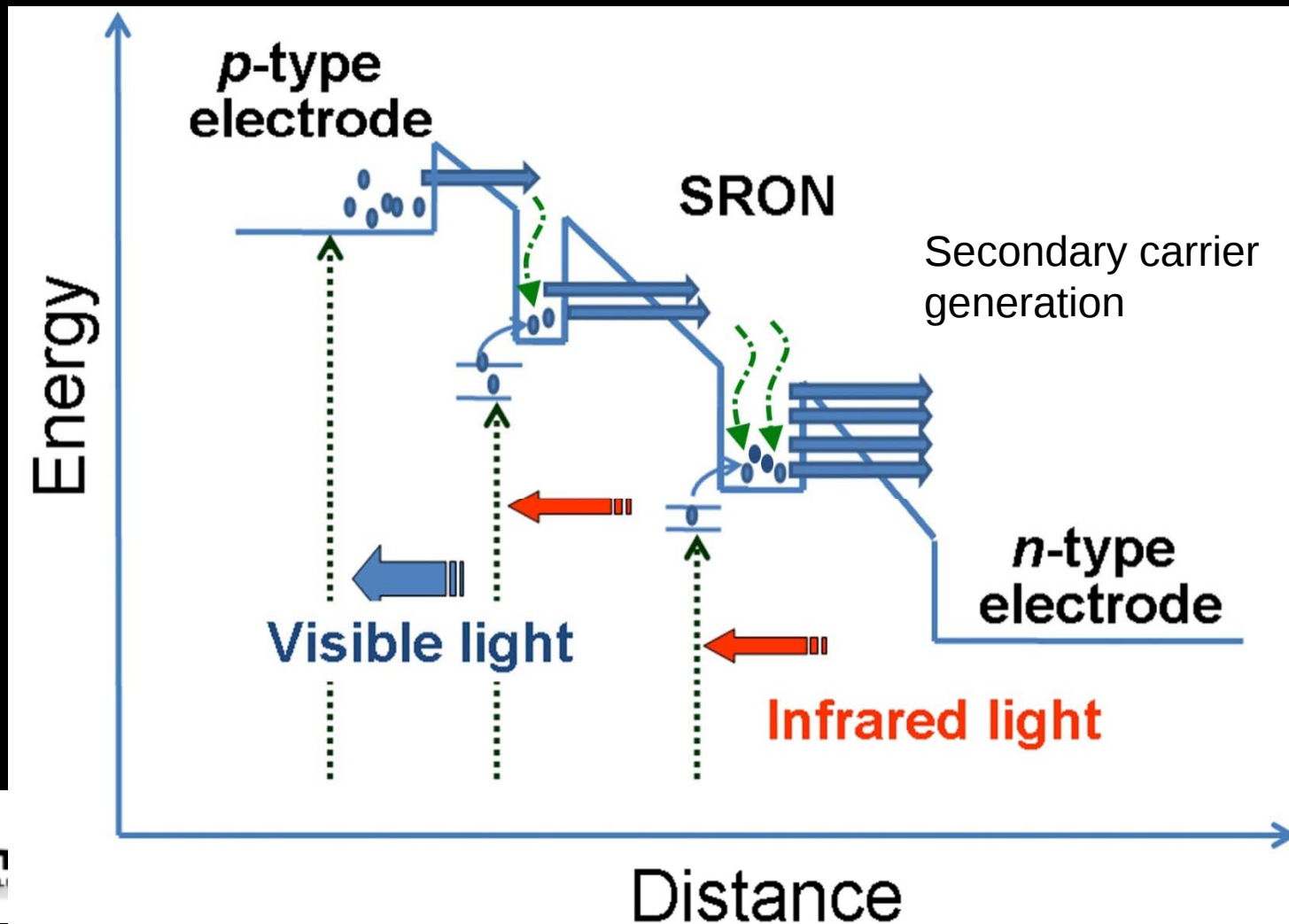
IR response in $\Gamma 3N$



IR response in $\Gamma 3N$



Solar cell with an internal gain mechanism



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Outline

- Silicon Photonics
- State of the art
- Silicon Photonics for lab-on-a-chip
- NanoSilicon photonics
- Conclusion



Conclusions:

- Silicon photonics is a mature technology
- Silicon photonics allows fabricating thousands of photonic components in a single chip
- Silicon photonics merges electronics and photonics to enable novel functionalities
- Silicon photonics is not only bulk Silicon (nanosilicon, strained silicon, silicon/germanium, germanium,)
- Silicon photonics is not only optical communication is much more



Bottom line:

- Each time the market catches size Silicon is the solution
- If you may want to compete with silicon, do not! Silicon will always make it





FP7 - 224312

HELIOS

pHotonics ELectronics functional
Integration on CMOS

Silicon photonics course

prepared by the HELIOS consortium

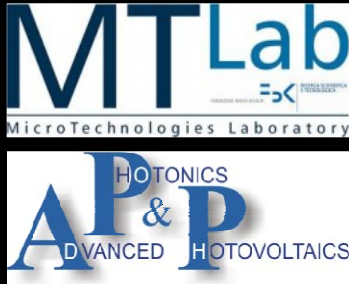
Download the course on <http://www.helios-project.eu/Download/Silicon-photonics-course>



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Acknowledgments



- EC: Helios, LIMA, Wadimos, Positive
- PAT: Gopsi, Naomi
- MAE: Italy-turkey, mexico, romania
- HCSC project and Optoi
- ITPAR



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Acknowledgments



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